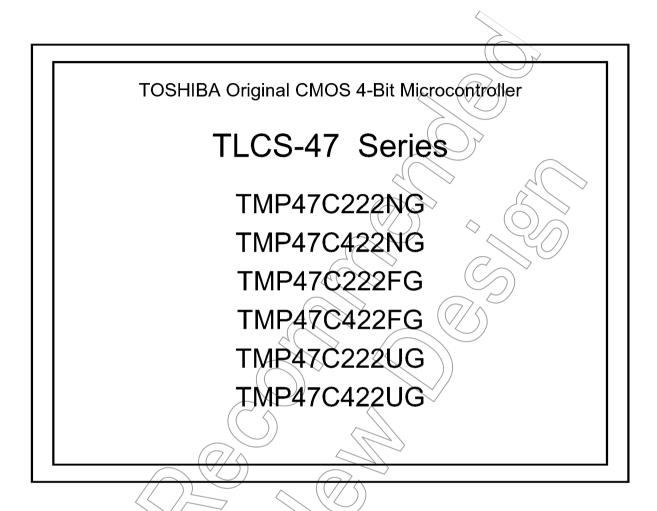
TOSHIBA



TOSHIBA CORPORATION

Semiconductor Company

Document Change Notification

The purpose of this notification is to inform customers about the launch of the Pb-free version of the device. The introduction of a Pb-free replacement affects the datasheet. Please understand that this notification is intended as a temporary substitute for a revision of the datasheet.

Changes to the datasheet may include the following, though not all of them may apply to this particular device.

1. Part number

Example: TMPxxxxxxFG

All references to the previous part number were left unchanged in body text. The new part number is indicated on the prelims pages (cover page and this notification).

2. Package code and package dimensions

Example: LQFP100-P-1414-0.50C (LQFP100-P-1414-0.50F)

All references to the previous package code and package dimensions were left unchanged in body text. The new ones are indicated on the prelims pages.

3. Addition of notes on lead solderability

Now that the device is Pb-free, notes on lead solderability have been added.

Ι

4. RESTRICTIONS ON PRODUCT USE

The previous (obsolete) provision might be left unchanged on page 1 of body text. A new replacement is included on the next page.

5. Publication date of the datasheet

The publication date at the lower right corner of the prelims pages applies to the new device.

1. Part number

2. Package code and dimensions

Previous Part Number (in Body Text)	Previous Package Code (in Body Text)	New Part Number	New Package Code	ОТР
TMP47C222N	P-SDIP42-600-1.78	TMP47C222NG	SDIP42-P-600-1.78	TMP47P422VNG
TMP47C422N	P-SDIP42-600-1.78	TMP47C422NG	SDIP42-P-600-1.78	TMP47P422VNG
TMP47C222F	P-QFP44-1414-0.80D	TMP47C222FG	QFP44-P-1414-0,80K	TMP47P422VFG
TMP47C422F	P-QFP44-1414-0.80D	TMP47C422FG	QFP44-P-1414-0.80K	TMP47P422VFG
TMP47C222U	P-QFP44-1010-0.80	TMP47C222UG	LQFP44-P-1010-0.80A	TMP47P422VUG
TMP47C422U	P-QFP44-1010-0.80	TMP47C422UG 〈	LQFP44-P-1010-0.80A	TMP47P422VUG

*: For the dimensions of the new package, see the attached Package Dimensions diagram.

3. Addition of notes on lead solderability

The following solderability test is conducted on the new device.

Lead solderability of Pb-free devices (with the G suffix)

Test	Test Conditions	Remark
Solderability	(1) Use of Lead (Pb) solder bath temperature = 230°C dipping time = 5 seconds the number of times = once use of R-type flux (2) Use of Lead (Pb)-Free solder bath temperature = 245°C dipping time = 5 seconds the number of times = once use of R-type flux	Leads with over 95% solder coverage fill lead forming are acceptable.

II

4. RESTRICTIONS ON PRODUCT USE

The following replaces the "RESTRICTIONS ON PRODUCT USE" on page 1 of body text.

RESTRICTIONS ON PRODUCT USE

20070701-EN

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set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc.

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• For a discussion of how the reliability of microcontrollers can be predicted, please refer to Section 1.3 of the chapter entitled Quality and Reliability Assurance/Handling Precautions.

5. Publication date of the datasheet

The publication date of this datasheet is printed at the lower right corner of this notification.

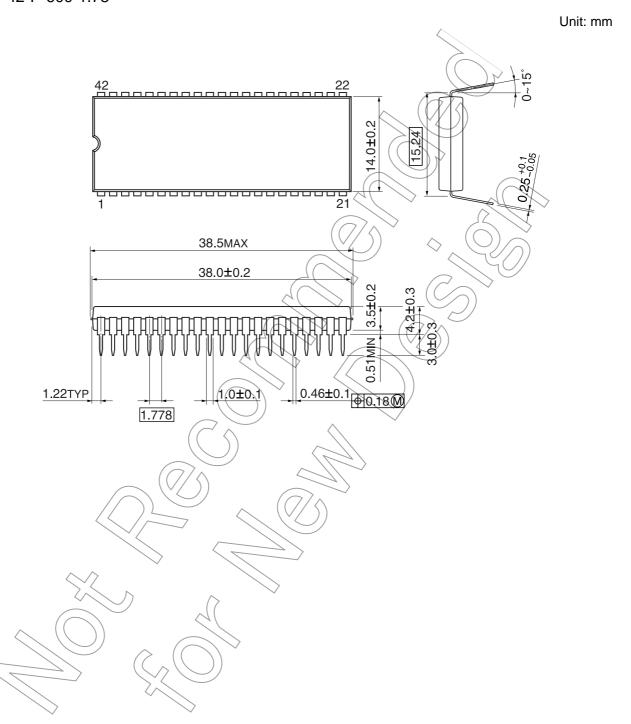


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(Annex)

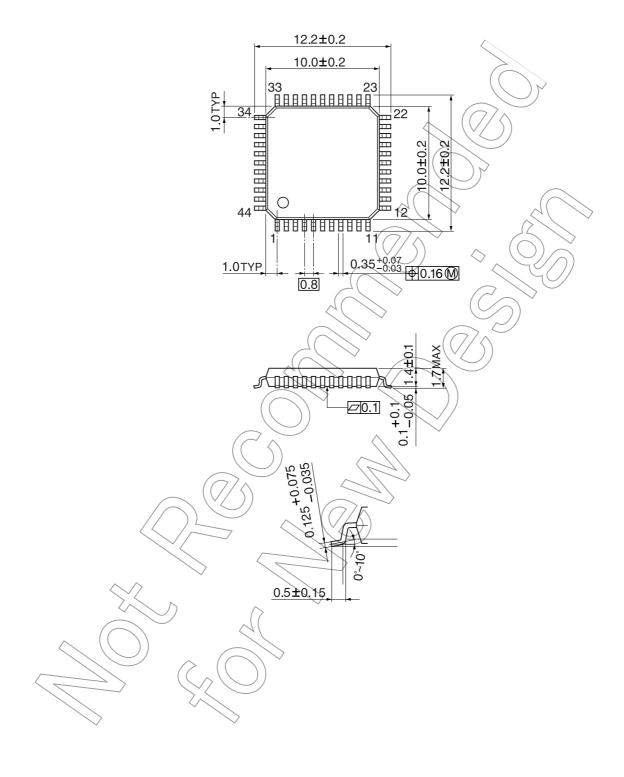
Package Dimensions

SDIP42-P-600-1.78



LQFP44-P-1010-0.80A

Unit: mm



CMOS 4-Bit Microcontroller

TMP47C222N, TMP47C422N TMP47C222F, TMP47C422F TMP47C222U, TMP47C422U

The TMP47C222/422 are high speed and high performance 4-bit single chip micro computers, integrating AD converter, pulse output, zero-cross detector and LCD driver based on the TLCS-470 series.

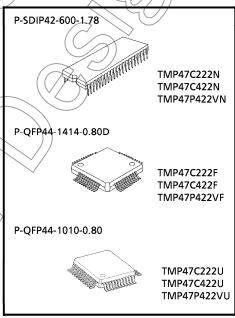
Part No.	ROM	RAM	Rackage	ОТР
TMP47C222N			P-SDIP42-600-1.78	TMP47P422VN
TMP47C222F	2048 × 8-bit	192 × 4-bit	P-QFP44-1414-0.80D	TMP47P422VF
TMP47C222U			P-QFP44-1010-0.80	TMP47P422VU
TMP47C422N			P-SDIP42-600-1.78	TMP47P422VN
TMP47C422F	4096 × 8-bit	256 × 4-bit	P-QFP44-1414-0.80D	TMP47P422VF
TMP47C422U			P-QFP44-1010-0.80	TMP47P422VU

Features

- ◆4-bit single chip microcomputer
- ♦ Instruction execution time: 1.0 μ s (at 8 MHz)
- ◆Low voltage operation: 2.2 V (at 4.2 MHz)
- ◆92 basic instructions
 - Table look-up instructions
- ◆Subroutine nesting: 15 levels max
- ◆6 interrupt sources (External: 2, Internal: 4) All sources have independent latches each, and multiple interrupt control is available.
- ◆I/O port (SDIP: 20 pins, QFP: 22 pins)
- ◆Interval Timer
- ◆Two 12-bit Timer/Counters

Timer, event counter, and pulse width measurement mode

- ◆Watchdog Timer
- ◆Serial Interface with 8-bit\buffer
 - Simultaneous transmission and reception capability
 - 8/4-bit transfer, external/internal clock, and leading/trailing edge shift mode



For a discussion of how the reliability of microcontrollers can be predicted, please refer to Section 1.3 of the chapter entitled Quality and Reliability Assurance / Handling Precautions.

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◆8-bit successive approximate type AD converter

• With sample and hold

• 4 analog inputs

• Conversion time: 24 μ s (at 8 MHz)

◆Pulse output

Buzzer drive/Remocon carrier

♦Zero-cross detector

♦LCD driver

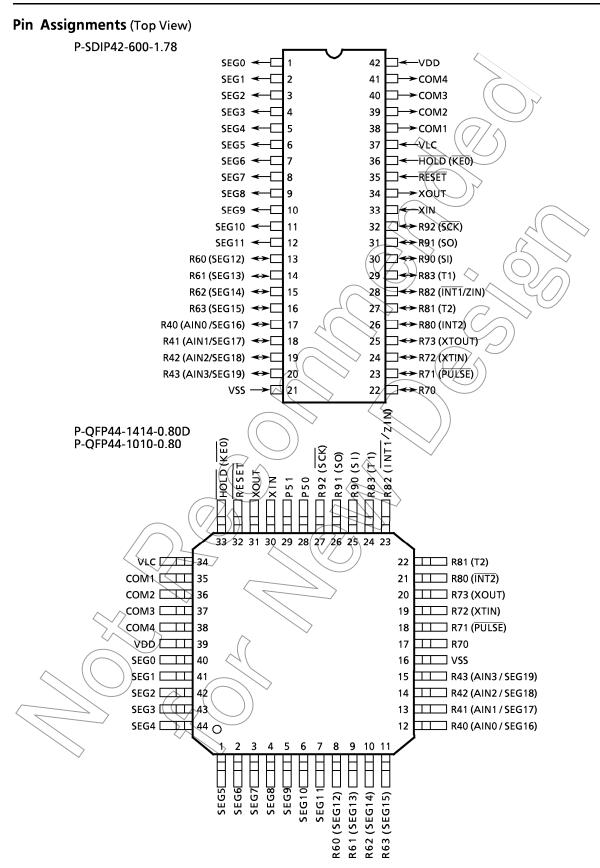
• LCD direct drive capability (max 10-digit display at 1/4 duty LCD)

• 1/4, 1/3, 1/2 duties or static drive are programmably selectable.

◆Dual-clock operation

High-speed / Low-power-consumption operating mode

◆Hold function
Battery/Capacitor back-up
◆Emulation pod: BM47C422



Pin Function

Pin Name	Input / Output	Function				
R43 (AIN3/SEG19) to R40 (AIN0/SEG16)	I/O (I/O)	4-bit I/O ports with latch (P5 port has only	AD converter analog input / LCD segment drive output			
P51, P50	Output	2-bit).	(Note)			
R63 (SEG15) to R60 (SEG12)	I/O (Output)	These ports can be set, cleared and tested <	LCD segment drive output			
R73 (XTOUT)	I/O (Output)	for each bit as specified by L-register	Resonator connecting pins			
R72 (XTIN)	I/O (Input)	indirect addressing bit manipulation	(Low-frequency).			
R71 (PULSE)	I/O (Output)	instruction.	Rulse output			
R70	1/0					
R83 (T1)		4-bit I/O ports with latch	Timer / Counter 1 external input			
R82 (INT1/ZIN)	. 1/0	When used as input port, external interrupt input pin, or timer/counter	External interrupt 1 and zero-cross input			
R81 (T2)	(Input)	external input pin, the latch must be set to	Timer / Counter2 external input			
R80 (ĪNT2)		"1".	External interrupt2 input			
R92 (SCK)	1/0 (1/0)	3-bit I/O ports with latch	Serial clock NO			
R91 (SO)	I/O (Output)	When used as input port or serial port, the	Serial data output			
R90 (SI)	I/O (Input)	latch must be set to "1".	Serial data input			
SEG11 to SEG0		LCD segment drive output	<i>\/</i>			
COM4 to COM1	Output	LCD Common drive output	<u> </u>			
XIN	Input	Resonator connecting pins (High-frequency)).			
хоит	Output	For inputting external clock, XIN is used and	XOUT is opened			
RESET	Input	Reset signal input				
HOLD (KEO)	I/O (Input)	HOLD request/release signal input	sense input			
VDD (VAREF)		+5V	AD converter analog reference voltage			
VSS (VASS)	Power Supply	0 V (GND)	AD converter analog reference voltage (GND)			
VLC	\ \n	LCD drive power supply				

Note: TMP47C222/422N (SDIP) do not have port P5.

Operational Description

Concerning the TMP47C222/422 the configuration and functions of hardware are described. The basic instruction of configuration in the TMP47C222/422 is the same as those of TLCS-470 series.

1. System Configuration

- ◆Internal CPU Function
 - 2.1 Program Counter (PC)
 - 2.2 Program Memory (ROM)
 - 2.3 H Register, L Register
 - 2.4 Data Memory (RAM)
 - a. Stack,
 - b. Stack Pointer Word (SPW),
 - c. Data Counter (DC)
 - 2.5 ALU, Accumulator
 - 2.6 Flags
 - 2.7 System Clock Controller
 - 2.8 Interrupt Controller
 - 2.9 Reset Controller
 - Watchdog Timer

◆ Peripheral Hardware Function

- 3.1 I/O Ports
- 3.2 Interval Timer
- 3.3 Timer/Counters (TC1, TC2)
- 3.4 Pulse output
- 3.5 Zero-cross detector
- 3.6 AD converter
- 3.7 Serial Interface
- 3.8 LCD Driver

2. Internal CPU Function

2.1 Program Counter (PC)

The program counter is a 12-bit binary counter which indicates the address of the program memory storing the next instruction to be executed. Normally, the PC is incremented by the number of bytes of the instruction every time it is fetched. When a branch instruction or a subroutine instruction has been executed or an interrupt has been accepted, the specified values listed in Table 2-1 are set to the PC. The PC is initialized to "0" during reset. In the TMP47C222/422, the long franch instruction [BSL a] should not be used.

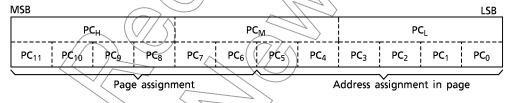


Figure 2-1. Configuration of Program Counter

The PC can directly address a 4096-byte address space. However, with the short branch and subroutine call instructions, the following points must be considered in the TMP47C222/422, the long branch instruction [BSL a] should not be used.

(1) Short branch instruction [BSS a]

In [BSS a] instruction execution, when the branch condition is satisfied, the value specified in the instruction is set to the lower 6 bits of the PC. That is, [BSS a] becomes the in-page branch instruction. When [BSS a] is stored at the last address of the page, the upper 6 bits of the PC point the next page, so that branch is made to the next page.

(2) Subroutine call instruction [CALL a]

In [CALL a] instruction execution, the contents of the PC are saved to the stack then the value specified in the instruction is set to the PC. The address which can be specified by the instruction consists of 11 bits and the most significant bit of the PC is always "0". Therefore, the entry address of the subroutine should be within an address range of 000_H through 7FF_H.

In	struction or	Condition	Program Counter (PC)				
Lo	peration		PC ₁₁ PC ₁₀ PC ₉ PC ₈ PC ₇ PC ₆ PC ₅ PC ₄ PC ₃ PC ₂ PC ₁ PC ₀				
u o	BS a	SF = 1 (Branch condition is satisfied)	Immediate data specified by the instruction				
t -		SF = 0 (Branch condition is not satisfied)	+ 2				
2		Lower 6-bit address # 111111	Hold Immediate data specified by the instruction				
l n s t	BSS a	Lower 6-bit address = 111111 (last address in page)	+ 1 Immediate data specified by the instruction				
_		SF = 0					
0	CALL a		0 Immediate data specified by the instruction				
. <u>-</u>	CALLS a		0 0 0 0 The data generated by the immediate 1 1 0				
ت ب	RET		The return address restored from stack				
9	RETI		The return address restored from stack				
×	Others		Incremented by the number of bytes in the instruction				
	errupt eptance		0 0 0 0 0 0 0 Interrupt vector 0				
	Reset		0 0 0 0 0 0 0 0 0 0				

Table 2-1. Status Change of Program Counter

2.2 Program Memory (ROM)

Programs and fixed data are stored in the program memory. The instruction to be executed next is read from the address indicated by the contents of the PC.

The fixed data can be read by using the table look-up

instructions.

Table look-up instructions

[LDL A, @DC], [LDH A, @DC+]

The table look-up instructions read the lower and upper 4 bits of the fixed data stored at the address specified in the data counter (DC) to place them into the accumulator. [LDL A, @DC] instruction reads the lower 4 bits of fixed data, and [LDH A, @DC+] instruction reads the upper 4 bits.

The DC is a 12-bit register, allowing it to address the entire program memory space.

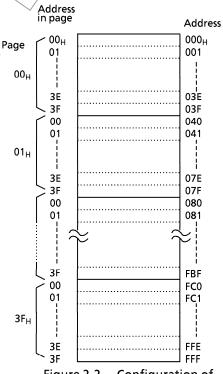


Figure 2-2. Configuration of Program Meory

2.2.1 Program Memory Capacity

Figure 2-3 shows the program memory map. Address 000_H to 086_H of the program memory are also used for special purposes.

2.2.2 Program Memory Map

The TMP47C222 has 2048 \times 8 bits (addresses 000_H to 7FF_H) of program memory (mask ROM), the TMP47C422 has 4096 \times 8 bits (addresses 000_H to FFF_H).

On the TMP47C222, no physical program memory exists in the address range 800 H to FFF_H. However, if this space is accessed by program, the most significant bit of each address is always regarded as "0" and the contents of the program memory corresponding to the address 000 H to 7FF_H are read.

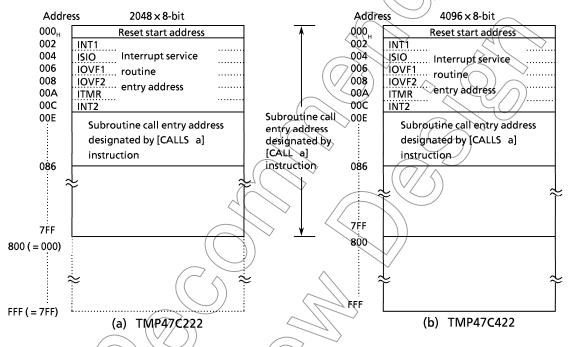


Figure 2-3. Program Memory Map

2.3 H Register and L Register

The H register and the L register are 4-bit general registers. They are also used as a register pair (HL) for the data memory (RAM) addressing pointer. The RAM consists of pages, each page being 16 words long (1 word = 4 bits). The H register specifies a page and the L register specifies an address in the page.

The L register has the auto-post-increment/decrement capability, implementing the execution of composite instructions. For example, [ST A, @HL+] instruction automatically increments the contents of the L register after data transfer.

During the execution of [SET @L], [CLR @L], or [TEST @L] instructions, the L register is also used to specify the bits corresponding to I/O port pins R73 through R40 (the indirect addressing of port bits by the L register).

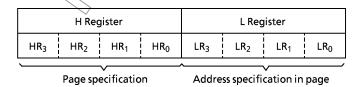


Figure 2-4. Configuration of H and L Registers

Example 1: To write immediate values "5" and "F" to data memory addresses 18_H and 11_H.

LD HL,#10H ; HL←10_H

ST #5,0HL+ ; RAM $[10_H] \leftarrow 5_H$, LR \leftarrow LR + 4ST #0FH,0HL+ ; RAM $[11_H] \leftarrow$ F_H, LR \leftarrow LR + 1

Example 2: The output latch of R71 pin set "1" by the L register.

LD L,#1101B

SET @L

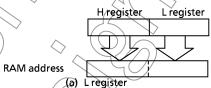
2.4 Data Memory (RAM)

The data memory stores user-processed data. One page of this memory is 16 words long (1 word = 4 bits). It has 16 pages.

The RAM is addressed in one of the three ways (addressing modes):

(1) Register-indirect addressing mode
In this mode, a page is specified by the H register
and an address in the page by the L register.

Example: LD A, @HL ; Acc←RAM [HL]



Instruction field

(b) Direct

RAM address

XXXX

xxxx

xxxx

 $x \times x \times$

(2) Direct addressing mode

In this mode, an address is directly specified by the 8 bits of the second byte (operand) in the instruction field.

Example: LD A, 2CH ; AcceRAM [2CH]

(3) Zero-page addressing mode
In this mode, an address in zero-page (addresses 00H through 0FH) is specified by the lower 4 bits of the second byte (operand) in the instruction field.



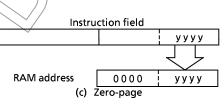
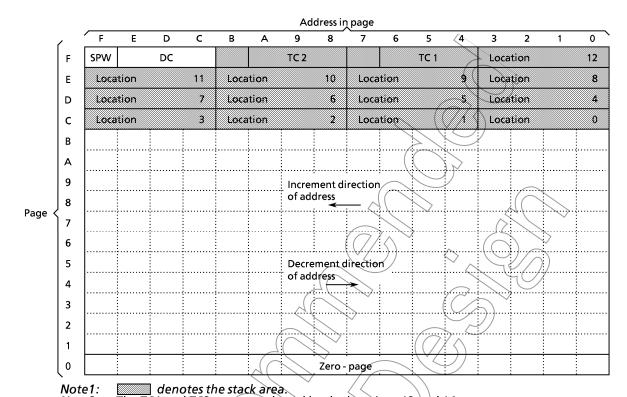


Figure 2-5. Addressing mode

2.4.1 Data Memory Map

Figure 2-6 shows the data memory map. The data memory is also used for the following special purpose.

- ① Stack and Stack Pointer Word (SPW)
- ② Data Counter (DC)
- 3 Count registers of the timer/counters (TC1, TC2)
- 4 Zero-page



ote2: The TC1 and TC2 areas are shared by the locations 13 and 14.

Figure 2-6. Data Memory Map

(1) Stack

The stack provides the area in which the return address is saved before a jump is performed to the processing routine at the execution of a subroutine call instruction or the acceptance of an interrupt. When a subroutine call instruction is executed, the contents (the return address) of the program counter are saved, when an interrupt is accepted, the contents of the program counter and flags are saved.

When returning from the processing routine, executing the subroutine return instruction [RET] restores the contents of the program counter from the stack; executing the interrupt return instruction [RETI] restores the contents of the program counter and flags.

The stack consists of up to 15 levels (locations 0 through 14) which are provided in the data memory (addresses CO_H through FB_H). Each location consists of 4-word data memory. Locations 13 and 14 are shared with the count registers of the timer/counters (TC1, TC2) to be described later.

The save/restore locations in the stack are determined by the stack pointer word (SPW). The SPW is automatically decremented after save, and incremented before restore. That is, the value of the SPW indicates the stack location number for the next save.

(2) Stack Pointer Word (SPW)

Address FF_H in the data memory is called the stack pointer word, which identifies the location in the stack to be accessed (save or restore).

Generally, location number 0 to 12 can be set to the SPW, providing up to 13 levels of stack nesting. Locations 13 and 14 are shared with the timer/counters to be described later; therefore, when the timer/counters are not used, the stack area of up to 15 levels is available. Address FF_H is assigned to the SPW, so that the contents of the SPW cannot be set "15" in any case.

The SPW is automatically updated when a subroutine call is executed or an interrupt is accepted. However, if it is used in excess of the stack area permitted by the data memory allocating configuration, the user-processed data may be lost. (For example, when the user-processed data area is in an address range 00_H through CF_H, up to location 4 of the stacks are usable. If an interrupt is accepted with location 4 already used, the user-processed data stored in addresses CC_H through CF_H corresponding to the location 3 area is lost.)

The SPW is not initialized by hardware, requiring to write the initial value (the location with which the use of the stack starts) by using the initialization routine. Normally, the initial value of "12" is used.

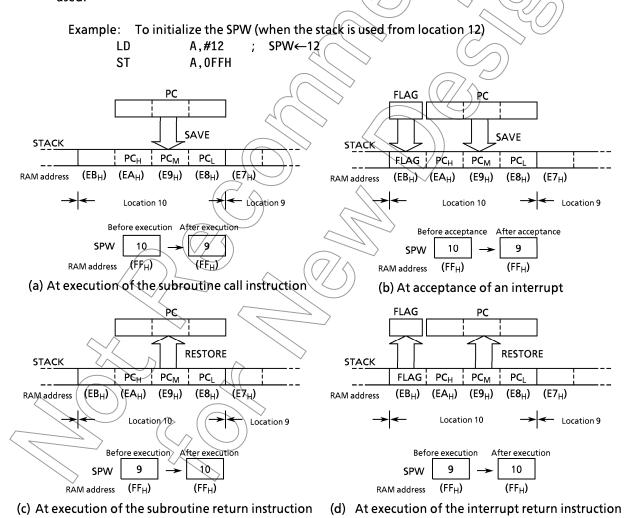


Figure 2-7. Accessing Stack (Save/Restore)

(3) Data Counter (DC)

The data counter is a 12-bit register to specify the address of the data table to be referenced in the program memory (ROM). Data table reference is performed by the table look-up instructions [LDL A, @DC] and [LDH A, @DC+]. The data table may be located anywhere within the program memory address space.

The DC is assigned with a RAM address in unit of 4 bits. Therefore, the RAM manipulation instruction is used to set the initial value or read the contents of the DC.

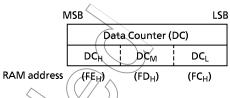


Figure 2-8. **Data Counter**

Example: To set the DC to 780H.

ST

HL,#0FCH Sets RAM address of DCL to HL register pair. LD

DC ← 780_H ST #0H,@HL+ ST #8H.@HL+ #7H,@HL+

(4) Count registers of the timer/counters (TC1, TC2)

The TMP47C222/422 has two channels of 12-bit timer/counters. (The count register of the timer/counter is assigned with a RAM addresses in unit of 4 bits, so that the initial value is set and the contents are read by using the RAM manipulation instruction.

The count registers are shared with the stack area (locations 13 and 14) described earlier, so that the stack is usable from location 13 when the timer/counter 1 is not used. When none of timer/counter 1 and timer/counter 2 are used, the stack is usable from location 14.

When both timer/counter 1 and timer/counter 2 are used, the data memory locations at addresses F7_H and FB_H can be used to store the user-processed data.

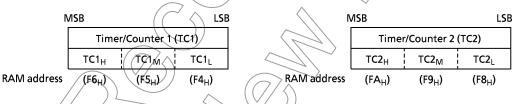


Figure 2-9. Count Registers of the Timer/Counters (TC1, TC2)

(5) Zero-page

The 16 words (at addresses 00H through 0FH) of the zero page of the data memory can be used as the user flags or pointers by using zero-page addressing mode instructions (comparison, addition, transfer, and bit manipulation), providing enhanced efficiency in programming.

To write immediate data "8" to address 09H if bit 2 at address 04H in the RAM is "1". Example: 04H,2 ; Skips if bit 2 at address 04_H in the RAM is "0". TEST B SKÍP ST #8,09H ; Writes "8" to address 09H in the RAM SKIP:

2.4.2 Data Memory Capacity

The TMP47C422 has 256 \times 4 bits (addresses 00_H to FF_H) of the data memory (RAM), and the TMP47C222 has 192×4 bits (addresses 00_H to $7F_H$, and $C0_H$ through FF_H).

When power-on is performed, the contents of the RAM become unpredictable, so that they must be initialized by the initialization routine.

Example: To clear RAM (use common to the TMP47C222 and TMP47C422)

LD HL, #00H; HL**←**00_H

SCLRRAM : ST #0, @HL+; RAM [HL] \leftarrow 0, LR \leftarrow LR +1

B SCLRRAM

ADD H, #1; HR←HR+1

B SCLRRAM

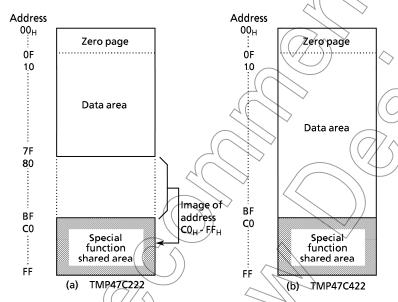
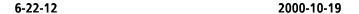


Figure 2-10. Data Memory Capacity and Address Assignment

Note: In the TMP47C222, the zero-page and thespecial function shared area (stack location 3 to 0) are overlapped. At programming, note that addresses 10 to 3FH are assigned to address 50 to 1FH in the TMP47C222. The technical data sheets for the TMP47P422V shall also be referred to.

Address 10 to 8FH should not be accessed.



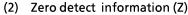
2.5 ALU and Accumulator

2.5.1 Arithmetic / Logic Unit (ALU)

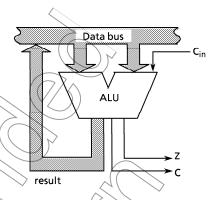
The ALU performs the arithmetic and logic operations specified by instructions on 4-bit binary data and outputs the result of the operation, the carry information (C), and the zero detect information (Z).

(1) Carry information (C)

The carry information indicates a carry-out from the most significant bit in an addition. A subtraction is performed as addition of two's complement, so that, with a subtraction, the carry information indicates that there is no borrow to the most significant bit. With a rotate instruction, the information indicates the data to be shifted out from the accumulator.



This information is "1" when the operation result or the data to be transferred to the accumulator/data memory is $"0000_B"$.



Note: C_{in} indicates the carry input specified by instruction

Figure 2-11. ALU

Example: The carry information (C) and zero detect information (Z) for 4-bit additions and subtractions.

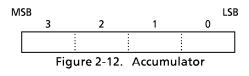
Operation	Result	Z Z
4 + 2 =	6 (0	0
7 + 9 =	0	[
8 - 1 =	7	0
2 - 2 =	0 ((\frac{1}{2})	1
5 - 8 =	- 3 (1101 _B)	0

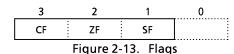
2.5.2 Accumulator (Acc)

The accumulator is a 4-bit register used to hold source data or results of the operations and data manipulations.

2.6 Flags

There are a carry flag (CF), a zero flag (ZF) and a status flag (SF), each consisting of 1 bit. These flags are set or cleared according to the condition specified by an instruction. When an interrupt is accepted, the flags are saved on the stack along with the program counter. When the [RETI] instruction is executed, the flags are restored from the stack to the states set before interrupt acceptance.





(1) Carry flag (CF)

The carry flag holds the carry information received from the ALU at the execution of an addition/subtraction with carry instruction, a compare instruction, or a rotate instruction. With a carry flag test instruction, the CF holds the value specified by it.

- ① Addition/subtraction with carry instructions [ADDC A, @HL], [SUBRC A, @HL] The CF becomes the input (C_{in}) to the ALU to hold the carry information.
- ② Compare instructions [CMPR A, @HL], [CMPR A, #k] The CF holds the carry information (non-borrow).

- ③ Rotate instructions [ROLC A], [RORC A] The CF is shifted into the accumulator to hold the carry information (the data shifted out from the accumulator).
- Carry flag test instructions [TESTP CF], [TEST CF]
 With [TESTP CF] instruction, the content of the CF is transferred to the SF then the CF is set to "1".
 With [TEST CF] instruction, the value obtained by inverting the content of the CF is

transferred to the SF then the CF is cleared to "0".

(2) Zero flag (ZF)

The zero flag holds the zero detect information (Z) received from the ALU at the execution of an operational instruction, a rotate instruction, an input instruction, or a transfer-to-accumulator instruction.

(3) Status flag (SF)

The status flag provides the branch condition for a branch instruction. Branch is performed when this flag is set to "1". Normally the SF is set to "1", so that any branch instruction can be regarded as an unconditional branch instruction. When a branch instruction is executed upon set or clear of the SF according to the condition specified by an instruction, this instruction becomes a conditional branch instruction. During reset, the SF is initialized to "1", other flags are not affected.

Example: When the following instructions are executed with the accumulator, H register, L register, data memory (address 07H), and carry flag being set to "CH", "0", "7", "5", and "1" respectively, the contents of the accumulator and flags become as follows:

Instruction	Acc after	Flag after execution			
instruction	execution	CF	ΣF	SF	
ADDC A, @HL	2 _H	1_	0	0	
SUBRC A, @HL	9 _H	0	(0 \	0	
CMPR A, @HL	C _H	6	<u>(</u>	1	
AND A, @HL	4 _H		0	1	
LD A, @HL	5 _H (/	// 1	0	1	

Instruction	Acc after	Flag after execution			
Instruction	execution	CF	ZF	SF	
LD A, #0	0 _H	1	1	1	
ADD A, #4	0 _H	1	1	0	
DEC A	B _H	1	0	1	
ROLC A	9 _H	1	0	0	
RORC A	E _H	0	0	1	

2.7 System Clock Controller

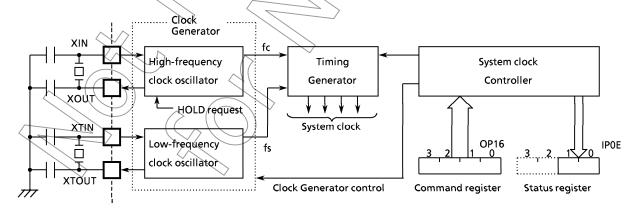


Figure 2-14. Clock Generator, Timing Generator and System Clock Controller

2.7.1 Clock Generator

The clock generator produces the basic clock pulses which provide the system clock to be supplied to the CPU and peripheral hardware. It contains two oscillators: a high-frequency clock oscillator and a low-frequency clock oscillator. Power consumption can be reduced by switching to the low power operation based on the low-frequency clock by the system clock controller. The high-frequency clock and the low-frequency clock can be easily obtained by attaching a resonator between the XIN and XOUT pins and the XTIN and XTOUT pins, respectively (At the high-frequency clock, RC oscillation is also posible, depending on the mask option). The system clock can also be obtained from the external oscillator.

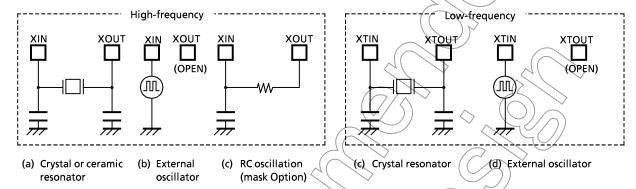


Figure 2-15. Examples of Resonator Connection

Note: Accurate adjustment of the oscillation frequency

Although no hardware to externally and directly monitor the clock pulse is not provided, the oscillation frequency can be adjusted by making the program to output the pulse with a fixed frequency to the port with the all interrupts disabled and timer/counters stopped and monitoring this pulse. With a system requiring the oscillation frequency adjustment, the adjusting program must be created beforehand.

Example: To abjust the High-frequency oscillation frequency output monitor pulse to R70 pin.

(fc = 40 [Hz])

SFCCHK: SEI %0P07, 0

Output wavefrom

NOP

CLR %0P07, 0

SFCCHK

2.7.2 Timing Generator (TG)

The timing generator produces the system clocks from clock pulse which are supplied to the CPU and peripheral hardweare.

The timing generater consists of a 19-stage binary counter with a divide-by-3 prescaler. The source clock to the timing generater and its input stage depend on the operating mode as shown below.

During reset, the binary counter is cleared to "0". However, the prescaler is not cleared.

- a. Single-clock mode
 - ① Normal-1 operating mode

 The CPU and the peripheral hardware are operated on the high-frequency clock. At reset release, this mode is set. In this mode, it is necessary to clear SLCK (bit 2 of command register OP16) to "0".
 - ② HOLD operating mode

 In this mode, the system operations are all stopped, holding the internal states valid immediately before the stop at the low power consumption level.

- b. Dual-clock mode
 - ① Normal-2 operating mode
 In this mode, the CPU is operated on the high-frequency clock but many peripheral hardware operate on the low-frequency clock.
 - ② SLOW operating mode
 In this mode, the high-frequency clock oscillation is stopped to operate the CPU and the peripheral hardware on the low-frequency clock, thereby reducing power consumption.

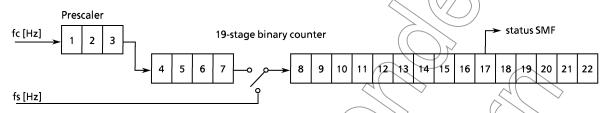


Figure 2-16. Configuration of Timing Generater

- (2) The timing generater provides the following functions:
 - ① Instruction cycle

- 4 Internal serial clock for a serial interface
- 2 Internal pulse for interval timer
- **S** Warm-up time at release of the hold operation
- 3 Internal pulse for timer/counters
- © Source clock for a watchdog timer

2.7.3 System Clock Controller

The system clock controller starts or stops the high-frequency and low-frequency clock oscillator and switches between the basic clocks. The operating mode is generally divided into the single-clock mode and the dual-clock mode, which are controlled by command.

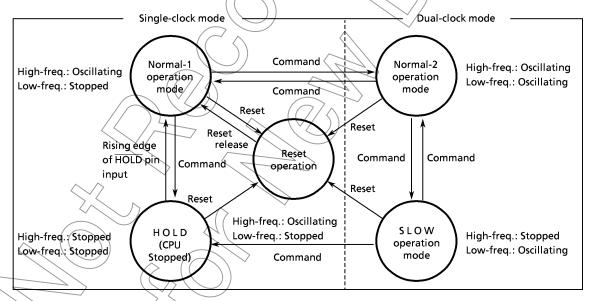


Figure 2-17. Operating Mode Transition Diagram

Note: Normal-1 and Normal-2 operating modes are sometimes referred to as the Normal operating mode collectively.

(1) System clock control

System clock control is performed by the command register (OP16). During reset, this register is initialized to "0" and the single-clock mode is selected.

Each state at operating mode switching can be read from the status register (IP0E).

System clock control command register (Port address: OP16) 3 2 DCLK1 (Initial value: 0000) DCLK3 **SLCK DWUT** DCLK3/DCLK1 Selects operation mode (Note 2) 00: Single clock mode (Normal-1 operating mode) 10: Dual clock mode (Normal-2 operating mode) 11: Dual clock mode (SLOW operating mode) Selects input clock for the eighth stage of TG (Note 3) **SLCK** 0: fc/2⁷ [Hz] 1: fs **DWUT** Sets the warm-up time (Note 4) Example: Αt fc = 4.19 MHz fs = 32,8 kHz 0: $2^{8}/fs + 2^{9}/fc$ [s] 7.9 [ms] 1: 2¹¹/fs + 2⁹ / fc 62.6 System clock control status register (Port address: IPOE) (SIOF) (SEF) SMF /HØLD/SLS Note1: fc; High-frequency clock [Hz] Low-frequency clock oscillating state SMF fs; Low-frequency clock [Hz] Note 2: the configuration of bits. (fc/217 or fc/210 [Hz]) Note 3: Only Normal-2 operating mode Note 4: Only switching from SLOW to Normal-2 HOLD / SLS HOLD pin state/operation state monitor Note 5: The access to command register (OP16) may cause the outputs over the eighth stage of Single-clock mode Dual-clock mode timing generator to precede that to be expected 0: HOLD pin at "H" level In Normal operation by maximum 27/fc or 1/fs [s]. 1: HOLD pin at "L" level In SLOW operation

Figure 2-18. System Clock Control Command Register/Status Register

(2) Instruction Cycle

The instruction execution and on-chip peripheral hardware operations are performed in synchronization with the basic clock. The smallest unit of instruction execution is called the "instruction cycle". The TLCS-470 series instruction set has 2 kinds of instructions, 1-cycle instruction and 2-cycle instruction. Each instruction cycle consists of 4 states (\$1 through \$4\$). Each state consists of 2 basic clock pulses.

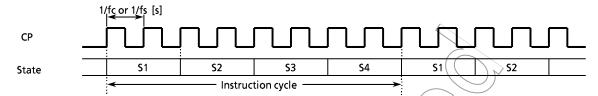


Figure 2-19. Instruction Cycle

2.7.4 Operation Mode

(1) Dual-clock mode

In this mode, the Normal-2 operation is generally performed by generating the instruction cycle from the high-frequency clock (fc). As required, the instruction cycle is generated by the low-frequency clock (fs), and the lower consumption power operation is performed by transferring SLOW operation to HOLD operation. The following describes the switching between the Normal-2, SLOW and HOLD operations in the dual clock mode. At reset, the command register is initialized to the single-clock mode. Since the low-frequency clock is not oscillated. Normal-2 operation in the dual clock mode must be set first. The low frequency clock starts oscillating by transferring to Normal-2 operation.

a. Switching from Normal-2 operation to SLOW operation

Setting DCLK1 (bit 1 of OP16) to "1" switches Normal-2 operation to SLOW operation. However it takes a few seconds to get a stable oscillation of the low-frequency clock. Therefore if there is possible to switch from Normal-2 operation to SLOW operation, wait until the low-frequency clock is stable or check the oscillation state by a program. SMF status (bit 1 of 1P0E) is available to check it.

When the high-frequency clock (fc/27) is input to the 8th stage of TG, first sets SLCK (bit 2 of OP16) to "1" ans input the low-frequency clock (fs). Then, SMF is monitored by a program. After confirming that SMF is changed "1" to "0" to "1" or "0" to "1" to "0", set DCLK1 to "1". At this time, the high-frequency clock oscillator stops.

b. Returning from SLOW operation to Normal-2 operation

Bit 2 of the command register is cleared to "0" and, at the same time, the warm-up time for return is set to DWUT. When the warm-up time has passed, the Normal-2 operation takes place. By monitoring SLS (bit 0 of the status register), the current operating mode can be known.

Note: The watchdog timer counter is used to count the warming up time.

To count certainly the warming up time, it is neccessary to initialize the counter. When switching from SLOW operation to Normal-2 operation, the watchdog timer must be cleared just before setting of the system clock control command register.

Example: Returning from SLOW operation to Normal-2 operation

LD A, #0000B OUT A, %0P15 LD A, #1100B OUT A, %0P16

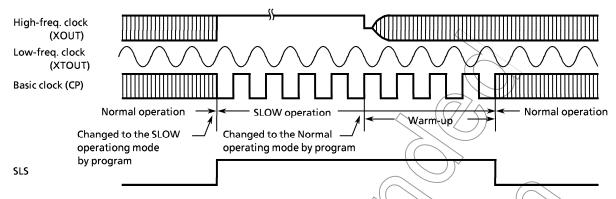


Figure 2-20. System Clock Switching Timing

c. Shifting from the SLOW operation to the HOLD operation

By setting the command in the command register (OP10), the low-frequency clock oscillation stops and the HOLD operation starts, refer to subsection "2.7.5 HOLD Operation MODE".

After being released the HOLD operation, the operation mode is NORMAL-1.

Note: In the HOLD and SLOW operating modes, the power consumed by the oscillator and the internal hardware is reduced. However, the power for the pin interface (depending on the external circuitry and program) is not directly associated with the low-power consumption operation. This must be considered in system design as well as interface circuit design.

(2) singl-clock mode

In this mode, only the high-frequency clock oscillator is used. Pins R72 (XTIN) and R73 (XTOUT) become the ordinary I/O port. The HOLD operating mode is available for reducing power consumption. It is controlled by the command register (OP10). In this mode, therefore, the system clock control command register (OP16) need not be manipulated. For the details of the HOLD operation, refer to Subsection "2.7.5 HOLD Operating Mode".

2.7.5 HOLD Operating Mode

The HOLD feature stops the system and holds the system's internal states active before stop with a low power. The HOLD operation is controlled by the command register (OP10) and the HOLD pin input. The HOLD pin input state can be known by the status register (IP0E or IP10).

Bit 0 of IPOE can be used in the single-clock mode. However the bit 0 of IOOE can not be used in the dual-clock mode, because the bit is used as the operating state monitor (SLS). To monitor the state of HOLD pin input in the dual-clock mode, use bit 3 of IP10. Bit 3 of IP10 can be used in the single-clock mode.

(1) Starts the HOLD operating mode

Setting the command to the command register starts HOLD operation in Normal-1 or SLOW mode. The following states keep during the HOLD operation.

- ① Oscillator stops and the systems internal operations are all held up.
- ② The interval timer is cleared to "0".
- The states of the data memory, registers, and latches valid immediately before the system is put in the HOLD state are all held.
- ① The program counter holds the address of the instruction to be executed after the instruction [out A, %OP10] or [OUT @HL, %OP10] which starts the HOLD operating mode.

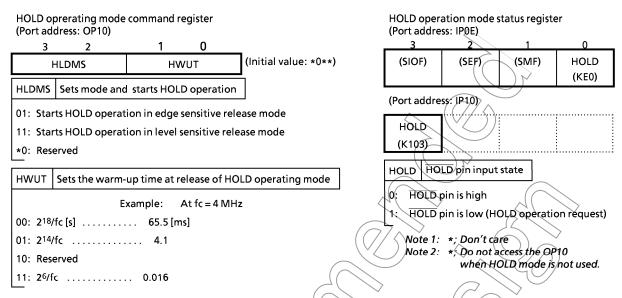


Figure 2-21. HOLD Operating Mode Command Register / Status Register

The HOLD operating mode consists of the level-sensitive release mode and the edge-sensitive release mode.

- a. Level-sensitive release mode
 In this mode, the HOLD operating is released by setting the HOLD pin to the high level. This mode is used for the capacitor backup with the main power off or for the battery backup for long hours.

 If the instruction to start the HOLD operation is executed with the HOLD pin input being high, the HOLD operation does not start but the clear sequence (warm-up) sets in immediately. Therefore, to start the HOLD operation in the level-sensitive mode, that the HOLD pin input is low (the HOLD operation request) must be recognized in program. This recognition is one of the two ways below:
 - 1 Testing HOLD (bit 0 of the status register)
 - ② Applying the HOLD pin input also to the INT1 pin to generate the external interrupt 1 request.

Example: To test HOLD to start the HOLD operation in the level-sensitive release mode (the warm-up time = 214/fc).

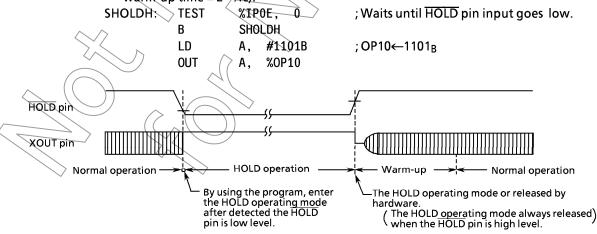


Figure 2-22. Level-sensitive Release Mode

b. Edge-sensitive release mode

In this mode, the HOLD operation is released at the rising edge of the HOLD pin input. This mode is used for applications in which a relatively short time program processing is repeated at a certain cycle. This cyclic signal (for example, the clock supplied from the low power dissipation oscillator). In the edge-sensitive release mode, even if the HOLD pin input is high, the HOLD operation is performed.

Example: To start the HOLD operation in the edge-sensitive release mode (the warm-up time = 214/fc).

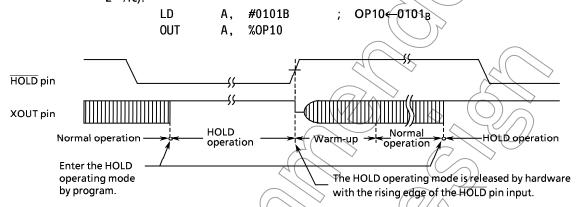


Figure 2-23. Edge-sensitive Release Mode

Note: In the HOLD operation, the dissipation of the power associated with the oscillator and the internal hardware is lowered; however, the power dissipation associated with the pin interface (depending on the external circuitry and program) is not directly determined by the hardware operation of the HOLD feature.

This point should be considered in the system design and the interface circuit design. In the CMOS circuitry, little current flows when the input level is stable at the power voltage level (V_{DD}/V_{SS}); however, when the input level gets higher than the power voltage level (by approximately 0.3 to 0.5 V), a current begins to flow. Therefore, if cutting off the output transistor at an I/O port (the open drain output pin with an input transistor connected) puts the pin signal into the high-impedance state, a current flow across the ports input transistor, requiring to fix the level by pull-up or other means.

(2) Releases the HOLD operating mode

The HOLD operating mode is released in the following sequence:

- 1) The high-freq. oscillator starts.
- Warm-up is performed to acquire the time for stabilizing oscillation. During the warm-up, the internal operations are all stopped. One of three warm-up times can be selected by program depending on the characteristics of the oscillator used.
- When the warm-up time has passed, an ordinary operation restarts from the instruction next to instruction which starts the HOLD operation.

The warm-up time is obtained by dividing the basic clock by the interval timer, so that, if the frequency at clearing the HOLD operation is unstable, the warm-up time shown in Figure 2-23 includes an error. Therefore, the warm-up time must be handled as an approximate value.

The HOLD operation is also released by setting the $\overline{\text{RESET}}$ pin to the low level. In this case, the normal reset operation follows immediately.

Note: To release the HOLD operation at a low hold voltage, the following points must be considerred:

To release the HOLD operation, the power voltage needs to be raised to the operating voltage level. If this is done, the RESET pin input, which is at the high level, also rises with the power voltage. In this case, if a time constant circuit or the like is externally attached, the rise of the RESET pin input voltage goes behind the rise of the power voltage. At this time, if the voltage level of the RESET pin input drops below the non-inverted high level input voltage of the RESET pin input (hysteresis input), the reset operation may occur.

2.8 Interrupt Function

(1) Interrupt Controller

There are 6 interrupt sources (2 external and 4 internal). The prioritized multiple interrupt capability is supported. The interrupt latches (IL₅ through IL₀) to hold interrupt requests are provided for the interrupt sources. Each interrupt latch is set to "1" when an interrupt request is made, asking the CPU to accept the interrupt. The acceptance of interrupt can be permitted or prohibited by program through the interrupt enable master flip-flop (EIF) and interrupt enable register (EIR). When two or more interrupts occur simultaneously, the one with the highest priority determined by hardware is serviced first.

Table 2-2. Interrupt Sources

			_ \ \ /		7 / ^	
	Interrupt Source		Priority	Interrupt Latch	Enable conditions	Entry address
External	Extenal Interrupt 1	(INT1)	(highest) 1	IL ₅	EIF = 1	002 _H
	Serial Interface Interrupt	(ISIQ)	2	IL ₄	EIF = 1, EIR ₃ = 1	004 _H
Internal	TC1 overflow Interrupt	(IOVF1)	3	II/3	EIF = 1, EIR ₂ = 1	006 _H
internal	TC2 overflow Interrupt	(IOVF2)	4	IL ₂		008 _H
	Interval Timer Interrupt	(LIMR)	(5)	IL ₁	EIF = 1, EIR ₁ = 1	00A _H
External	External Interrupt 2	(INT2)	(lowest) 6	IL ₀	EIF = 1, EIR ₀ = 1	00C _H

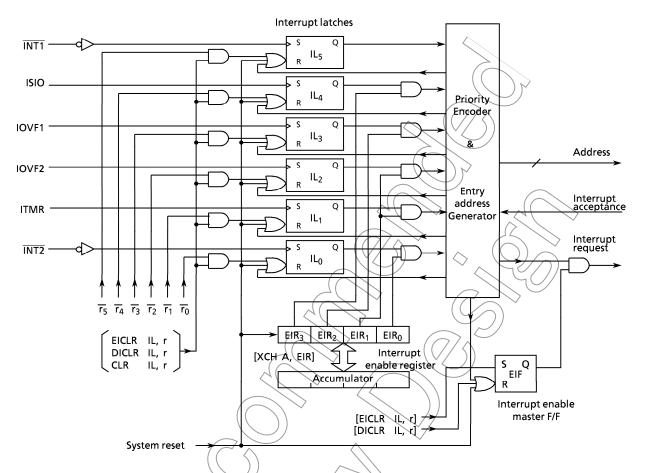


Figure 2-24. Interrupt Controller Block Diagram

a. Interrupt enable master flip-flop (EIF)

The EIF controls the enable/disable of all interrupts. When this flip-flop is cleared to "0", all interrupts are disabled; when it is set to "1", the interrupts are enabled.

When an interrupt is accepted, the EIF is cleared to "0", temporarily disabling the acceptance of subsequent interrupts. When the interrupt service program has been executed, the EIF is set to "1" by the execution of the interrupt return instruction [RETI], being put in the enabled state again.

Set or clear of the EIF in program is performed by instructions [EICLR IL, r] and [DICLR IL, r], respectively. The EIF is initialized to "0" during reset.

b.Interrupt enable register (EIR)

The EIR is a 4-bit register specifies the enable or disable of each interrupt except INT1. An interrupt is enabled when the corresponding bit of the EIR is "1", and an interrupt is disabled when the corresponding bit of the EIR is "0". Bit 1 of the EIR (EIR₁) is shared by both IOVF2 and ITMR interrupts. Read/write on the EIR is performed by executing [XCH A, EIR] instruction. The EIR is initialized to "0" during reset.

c. Interrupt latch (IL)

An interrupt latch is provided for each interrupt source. The IL is set to "1" when an interrupt request is made to ask the CPU for accepting the interrupt. Each IL is cleared to "0" upon acceptance of the interrupt. It is initialized to "0" during reset.

The ILs can be cleared independently by interrupt latch operation instructions ([EICLR IL, r], [DICLR IL, r], and [CLR IL, r]) to make them cancel interrupt requests or initialize by program. When the value of instruction field (r) is "0", the interrupt latch is cleared; when the value is "1", the IL is held. Note that the ILs cannot be set by instruction.

Example 1: To enable IOVF1, INT1, and INT2 interrupts.

LD A,#0101B ; EIR←0101_B

XCH A.EIR

EICLR IL,111111B; EIF←1

Example 2: To set the EIF to "1", and to clear the interrupt latches except ISIO to "0".

EICLR IL,010000B; $E|F \leftarrow 1$, $|L_5 \leftarrow 0$, $|L_3 \rightarrow |L_0 \leftarrow 0|$

(2) Interrupt Processing

An interrupt request is held until the interrupt is accepted or the IL is cleared by the reset or the interrupt latch operation instruction. The interrupt acknowledge processing is performed in 2 instruction cycles after the end of the current instruction execution (or after the timer/counter processing if any). The interrupt service program terminates upon execution of the interrupt return instruction [RETI].

The interrupt acknowledge processing consists of the following sequence:

- ① The contents of the program counter and the flags are saved on the stack.
- ② The interrupt entry address corresponding to the interrupt source is set to the program counter.
- 3 The status flag is set to "1".
- **4** The EIF is cleared to $^{\circ}0''$, temporarily disabling the acceptance of subsequent interrupts.
- ⑤ The interrupt latch for the accepted interrupt source is cleared to "0".
- © The instruction stored at the interrupt entry address is executed. (Generally, in the program memory space at the interrupt entry address, the branch instruction to each interrupt processing program is stored.)

To perform the multi-interrupt, the EIF is set to "1" in the interrupt service program, and the acceptable interrupt source is selected by the EIR. However, for the INT1 interrupt, the interrupt service is disabled under software control because it is not disabled by the EIR.

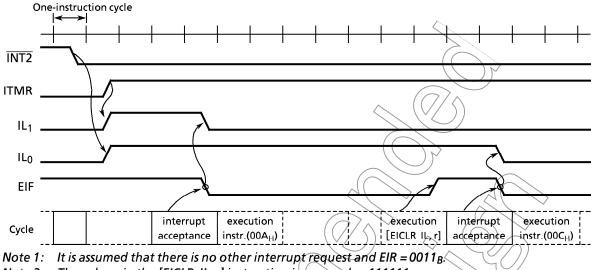
Example: The INT1 interrupt service is disabled under software control (Bit 0 of RAM [05_H] are assigned to the disabling switch of interrupt service).

PINT1: TEST 05H, 0 ; Skips if RAM [05H] 0 is "1"

B SINT1

SINT1:

6-22-24 2000-10-19



Note 2: The value r in the [EICLR IL, r] instruction is assumed as 111111B.

Note 3: [____] denotes the execution of an instruction.

Figure 2-25. Interrupt Timing Chart (Example)

The interrupt return instruction [RETI] performs the following operations:

- ① Restores the contents of the program counter and the flags from the stack.
- Sets the EIF to "1" to provide the interrupt enable state again.

Note: When the time required for the interrupt service is longer than that foe the interrupt request, only the interrupt service program is executed without executing the main program.

In the interrupt processing, the program counter and flags are automatically saved or restored but the accumulator and other registers are not. If it is necessary to save or restore them, it must be performed by program as shown in the following example. To perform the multi-interrupt, the saving RAM area never be overlapped.

Example: To save and restore the accumulator and HL register pair.

XCH HL, GSAV1 ; RAM [GSAV1] ↔ HL XCH A, GSAV1+2 ; RAM [GSAV1+2] ↔ Acc

Note: The lower 2 bits of GSAV1 should be "0's".

(3) External Interrupt

When an external interrupt (INT1 or INT2) occurs, the interrupt latch is set at the falling edge of the corresponding pininput (INT1 or INT2).

Because the external interrupt input is the hysteresis type, each of high and low level time requires 2 or more instruction cycles for a correct interrupt operation.

the INT1 interrupt cannot be disabled by the EIR, so that it is always accepted in the interrupt enable state (EIF = "1"). Therefore, INT1 is used for an interrupt with high priority such as an emergency interrupt. When R82 (INT1) pin is used for the I/O port, the INT1 interrupt occurs at the falling edge of the pin input, so that the interrupt return [RETI] instruction must be stored at the interrupt entry address to perform dummy interrupt processing.

The INT2 interrupt can be enable/disable by the EIR. Therefor, the INT2 interrupt occurs at the falling edge of the pin input when R80 (INT2) pin is used for the I/O port.

But bit 0 of the EIR is only kept at "0" not accepting the interrupt request.

2.9 Reset Function

When the RESET pin is held to the low level for three or more instruction cycles when the power voltage is within the operating voltage range and the oscillation is stable, reset is performed to initialize the internal states.

When the $\overline{\text{RESET}}$ pin input goes high, the reset is cleared and program execution starts from address 000_H . The $\overline{\text{RESET}}$ pin is a hysteresis input with a pull-up resistor (220 k Ω typ.). Externally attaching a capacitor and a diode implement a simplified power-on-reset operation.

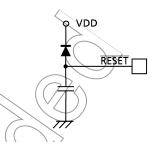


Figure 2-26. Simplified Power-On-Reset Circuit

Table 2-3. Initialization of Internal States by Reset Operation

On-chip hardware	Initial value	On-chip hardware Initial value	
Program counter (PC)	000 _H		\Box
Status flag (SF)	1	Output latch (I/O ports or Output ports) Refer to "INPUT/OUTPU"	т
Interrupt enable master flip-flop (EIF)	0 (Circuitry".	
Interrupt enable register (EIR)	0 _H	Refer to the	
Interrupt latch (IL)	"0"	Command register description of each relative	
Interval timer	"o"	command regis	ter.

2.9.1 Watchdog Timer (WDT)

The watchdog timer capability is provided to quickly detect the CPU malfunction such as endless looping caused by noises or the like, and restore the CPU to the normal state. The WDT is disabled during reset. The WDT consists of 10 binary counters, a flip-flop, and a controller. Source input clock of binary counters is fc/2¹⁵[Hz]. The flip-flop is set to "1" during reset, and cleared to "0" on the rising edge of the binary counter output. The WDT is controlled by the command register (OP15). The command register is initialized to "1000g" during reset.

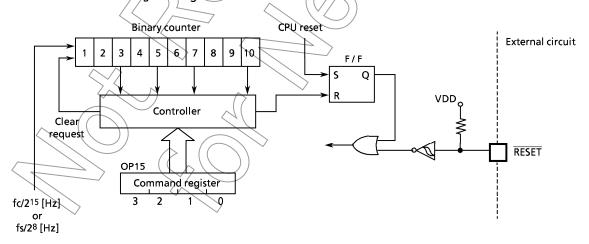
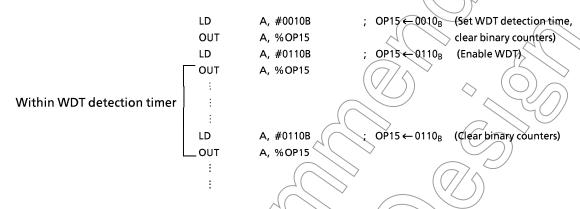


Figure 2-27. Configuration of Watchdog Timer

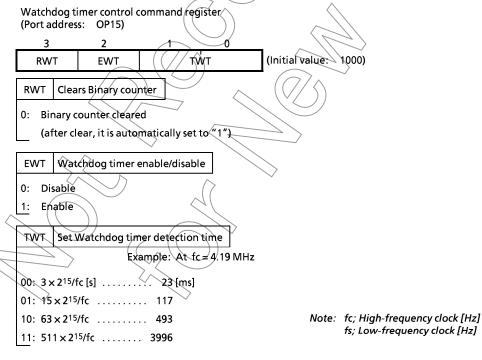
To detect the CPU malfunction by the WDT:

- ① Set the WDT detection time, and clear the binary counters.
- 2 Enable the WDT.
- ③ Clear the binary counters within WDT detection time that was set in ①. If a CPU malfunction occurs, preventing the binary counters from being cleared, the flip-flop is clearred to "0" on the rising edge of the binary counter output, making the malfunction detection signal active.

Example: To enable the with detection time of $63 \times 2^{15}/f_c$ [s]



Note: It is necessary to clear the binary counter prior to enabling watchdog timer. Further, the Watchdog Timer should be disable by program during warm-up time from SLOW operating mode to Normal-2 operating mode.



(a) Command Register

T) A /T	Normal-1	Normal-2 operation		CLOVA.	fc = 4.194304 MHz,
TWT	operation	$SLCK = 0 (fc / 2^7)$	SLCK = 1 (fs)	SLOW	fs = 32.768 kHz
00	3×2 ¹⁵ /fc [s]		3×2 ⁸ /1	23.4 [ms]	
01	15×	2 ¹⁵ / fc	15 × 2 ⁸ /1	((117)	
10	63 × 2 ¹⁵ / fc		63 × 2 ⁸ /fs		492
11	511 × 2 ¹⁵ / fc		511 × 2 ⁸ /fs		√∖3992

(b) WDT detection timer

Figure 2-28. Watchdog Timer Control Command Register

3. Peripheral Hardware Function

3.1 Ports

The data transfer with the external circuit and the command/status/data transfer with the internal circuit are performed by using the I/O instructions (13 kinds). There are 4 types of ports:

① I/O port ; Data transfer with external circuit

2 Command register ; Control of internal circuit

Status register ; Reading the status signal from internal circuit

4 Data register ; Data transfer with internal circuit

These ports are assigned with port addresses (00_H through 1F_H). Each port is selected by specifying its port address in an I/O instruction. Table 3-2 lists the port address assignments and the I/O instructions that can access the ports.

3.1.1 I/O Timing

(1) Input timing

External data is read from an input port or an I/O port in the S3 state of the second instruction cycle during the input instruction (2-cycle instruction) execution. This timing cannot be recognized from the outside, so that the transient input such as chattering must be processed by program.

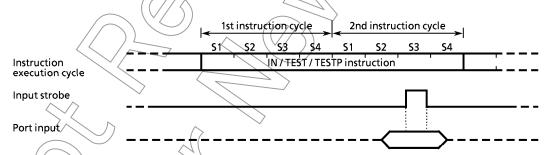


Figure 3-1. Input Timing

(2) Output timing

Data is output to an output port or an I/O port in the S4 state of the second instruction cycle during the output instruction (2-cycle instruction) execution.

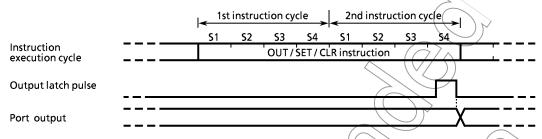


Figure 3-2. Output Timing

3.1.2 I/O Ports

TMP47C222/422 have 7 I/O ports (22 pins) each as follows:

① R4 ; 4-bit input/output (shared with AD converter analog inputs)

② P5 ; 2-bit output ③ R6 ; 4-bit input/output

♠ R7 ; 4-bit input/output (shared with low-frequency resonator)

connecting pins and pulse output)

4-bit input/output (shared with zero-cross input, external interrupt)

© R8 ; 4-bit input/output (shared with zero-cross input, external interrup input and timer/counter input)

© R9 ; 3-bit input/output (shared with serial port)

Each output port contains a latch, which holds the output data. The input ports have no latch; therefore, it is desired to hold data externally until it is read or read twice or more before processing it.

(1) Ports R4, R5, R6 and R7

These ports are 4-bit I/O ports with a latch (Port R5 is 2-bit). When used as an input port, the latch must be set to "1". The latch is initialized to "1" during reset.

These 4 ports (14 pins) can be set, cleared, and tested for each bit as specified by L register indirect addressing bit manipulation instructions ([SET @L], [CLR @L], and [TEST @L]). Table 3-1 lists the pins (I/O ports) that correspond to the contents of L register.

Example: To clear R43 output as specified by the L register indirect addrressing bit manipulation instruction.

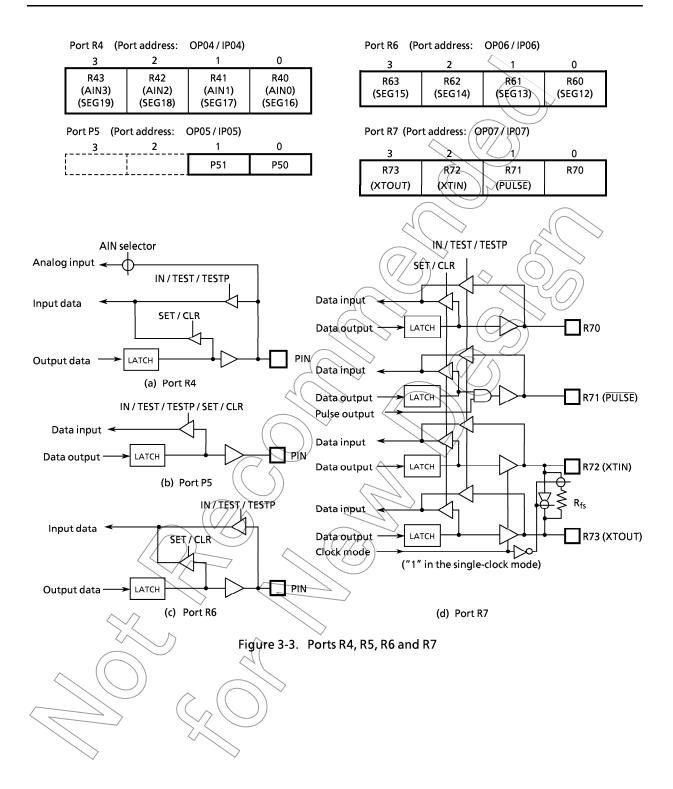
LD L, #0011B ; Sets R43 pin address to L register

Table 3-1. Relationship between L register contents and I/O port bits

$\overline{}$	$\overline{}$	_	\				_	_	_	
	. rec	giste	er	PIN (\langle	^	rég	giste) PIN
М	2	1	0	<i>\</i>		/3/	2	+/	9	
/0	Q	Q	0	R40	4	/0	1	0	0	P50
0	0	o	1	R41		0	1	0	1	P51
0	0	1	0	R42						
0	0	1	1	R43						

L	. reg	giste	er	PIN
3	2	1	0	1 114
1	0	0	0	R60
1	0	0	1	R61
1	0	1	0	R62
1	0	1	1	R63

L	. reg	giste	er	PIN
3	2	1	0	
1	1	0	0	R70
1	1	0	1	R71
1	1	1	0	R72
1	1	1	1	R73



(a) Port R4 (R43 to R40)

Port R4 is 4-bit I/O port with latch shared by the analog inputs for AD converter and LCD segment output. When used as an analog inputs or segment output, the latch should be set to "1". If other port is used as an output, be careful not to execute the output instruction for any port during AD conversion in order to keep accuracy of conversion. The latch is initialized to "1" and analog input is selected R40 (AINO) pin during reset.

(b) Port P5 (P51, P50)

Port P5 is 2-bit output port with a latch. When an input instruction is executed, the latch data is read. The latch is initialized to "1" during reset. Port P5 is only QFP package type.

(c) Port R6 (R63 to R60)

Port R6 is 4-bit I/O port with latch shared by the LCD segment output. When used as segment output, the latch should be set to "1". The latch is initialized to "1" during reset.

(d) Port R7 (R73 to R70)

Port R7 is shared by the low-frequency resonator connection pins (XTIN, XTOUT) and the pulse output pin (PULSE). For the dual-clock mode operation, the low-frequency resonator (32.768 kHz) is connected to R72 (XTIN) and R73 (XTOUT) pins. For the single-clock mode operation, R72 and R73 pins are used for the ordinary I/O ports. When the pulse output is used, R71 (PULSE) becomes the pulse output pin. The pulse output is the logical AND output with the port R71 output latch. To use the R71 pin for an ordinary I/O port, the pulse output must be disabled.

(2) Port R8 (R83 to R80)

Port R8 is a 4-bit I/O port with a latch. When used as an input port, the latch must be set to "1". The latch is initialized to "1" during reset.

Port R8 is shared with the external interrupt input pin and the timer/counter input pin. To use this port for one of these functional pins, the latch should be set to "1". To use it for an ordinary I/O port, the acceptance of external interrupt should be disabled or the event counter/pulse width measurement modes of the timer/counter should be disabled.

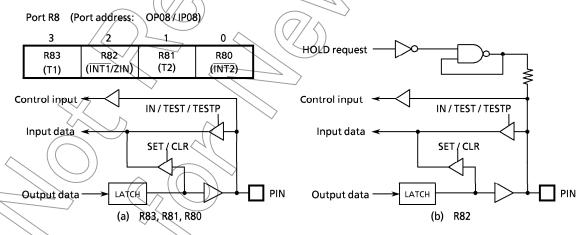


Figure 3-4. Port R8

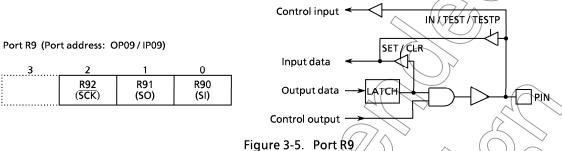
Note: When R82 (INT1) pin is used for an I/O port, external interrupt 1 occurs upon detection of the falling edge of pin input, and if the interrupt enable master flip-flop is enabled, the interrupt request is always accepted. So that a dummy interrupt processing must be performed (only the interrupt return instruction [RETI] is executed).

With R80 (INT2) pin, external interrupt 2 occurs like R82 in but bit 0 of the interrupt enable register (EIR₀) is only kept at "0", not accepting the interrupt request.

(3) Port R9 (R92 to R90)

Port R9 is a 3-bit I/O port with a latch. When used as an input, the latch must be set to "1". The latch is initialized to "1" during reset. Port R9 is shared with the serial port. To use port R9 for the serial port, the latch should be set to "1".

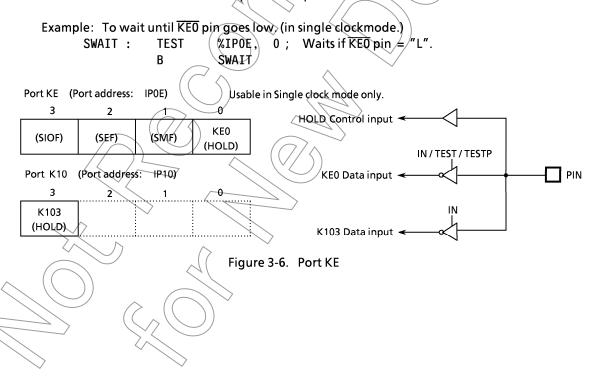
Although R93 pin does not exist actualy. However, other instructions can be used, in which an undefined value is read upon execution of an input instruction.



- (:[22)

(4) Port KE (KEO)

Port KE is a 1-bit sense input port shared by the hold request/release signal input pin (HOLD). This input port is assigned to the least significant bit of port address IP0E or the most significant bit of port address IP10 and both input data is processed as the data with inverted polarity. For example, if an input instruction is executed with the pin on the high level, "0" is read. Note that KEO input cannot be used in the dual-clock mode because KEO input monitors the states of SLOW operation mode. To monitor the states of HOLD pin K103 input.



																					_ <				
	SET @L CLR @L TEST @L	1		ļ	00	00	0	i I		I		ı		I		I	ļ		1	1	1	-(> (
į	TEST %p, b	ı		ı	00	00	00	00	ı	. 1	-	0	ı	1	1	!						7/) ,	
tion	SET %p, b CLR %p, b	-			00	00	00	00	ı	1 1	ı	1	-		1	1			//-//))	1	ı	1	
Input/Output instruction	OUTB @HL	1		I	ı	i !	ı		1	1 [į	1 1	(7			1	1	\Diamond	· <	\		て フ て
Input/C	OUT #k, %p		: !	ı	00	00	00	0	i		\ 	60			, :	·	l	ı				コンノ			\
	OUT A, %p OUT @HL,%p	-		ļ	00	00	00	00	4((1((-//		<i>\$</i> 0	> 0	1 (0		- 94	5,e			/)() C) (
	IN %p, A IN %p, @HL	_	1 1	ı	00		30	\ \ \			~	00	0	I C		_	/_	>>	//	1	I	ı	1	l l	ı
T.	Output (Op**)	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	M)		R4 output port	R6 output port	R7 output port	R9 output port	\ \ \ +			LCD output resistance selector Serial transmit buffer	Hold operating mode control	——————————————————————————————————————	A/D start register		Watchdog timer control	System clock control Pulse output control		Interval Timer interrupt control	LCD driver control 1	LCD driver control 2	Imer/Counter 1 control	Ilmer/counter z control Serial interface control 1	Serial interface control 2
pod ())	Input (ip**)			3	R4 input port (Analog input)	< (R7 input port	>				SIO, HOLD status Serial receive buffer		anley battavor 0/V	A/D status input										
Port	address (**)	н ₀₀	5 6	03	4 0 0	90	07	60	0A	00	Q0	0E 0F	10 _H	11	13.	14	15	17	18	19	1 4	B (ب ر	5 1	1

Note 1: "——" means the reserved state. Unavailable for the user programs. Note 2: Do not use the set and clear instructions with bit 3 of the OP09.

3.2 Interval Timer

The interval timer can be used to generate an interrupt with a fixed frequency. An interval timer interrupt is controlled by the command register (OP19). And the command resister (OP19) is initialized to "0" during reset. An interval timer interrupt is generated at the first rising edge of the binary counter output after the command has been set. The interval timer is not cleared by command, so that the first interrupt may occur earlier than the preset interrupt period.

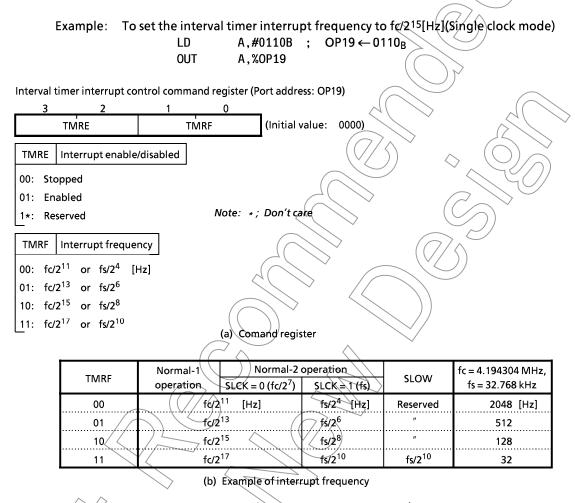


Figure 3-7. Interval Timer Interrupt Command Register

3.3 Timer/Counters (TC1, TC2)

The TMP47C222/422 contains two 12-bit timer/counters. RAM addresses are assigned to the count register in unit of 4 bits, permitting the initial value setting and counter reading through the RAM mauipulation instruction.

When the timer/counter is not used, the mode selection may be set to "stopped" to use the RAM at the address corresponding to the timer/counter for storing the ordinary use-processed data.

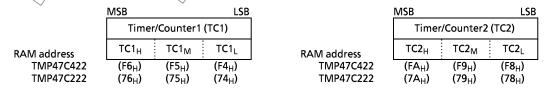


Figure 3-8. The Count Registers of the Timer/Counters (TC1, TC2)

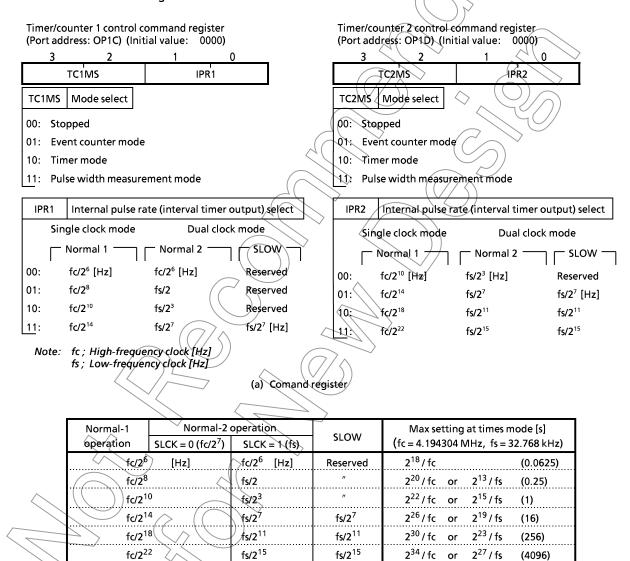
3.3.1 Functions of Timer/Counters

The timer/counters provide the following functions:

- ① Event counter
- 2 Programmable timer
- 3 Pulse width measurement

3.3.2 Control of Timer/Counters

The timer/counters are controlled by the command registers. The command register is accessed as port address OP1C for timer/counter 1, and port address OP1D for timer/counter 2. These registers are initialized to "0" during reset.



(b) Internal palse rate and Max. setting time at timer mode

Figure 3-9. Timer/Counter Control Command Register

The timer/counter increments at the rising edge of each count pulse. Counting starts with the first rising edge of the count pulse generated after the command has been set. Count operation is performed in 1 instruction cycle after the current instruction execution, during which the execution of a next instruction and the acceptance of an interrupt are delayed. If counting is requested by both TC1 and TC2 simultaneously, the request by TC1 is preferred. The request from TC2 is accepted in the next instruction cycle. Therefore, during a count operation, the apparent instruction execution speed drops as counting occurs more frequently. The timer/counter causes an interrupt upon occurrence of an overflow (a transition of the count value from FFF_H to 000_H). If the timer/counter is during the interrupt enabled state and the overflow interrupt is accepted immediately after its occurrence, the interrupt is processed in the sequence shown in Figure 3-10. Note that counting continues if there is a count request after overflow occurrence.

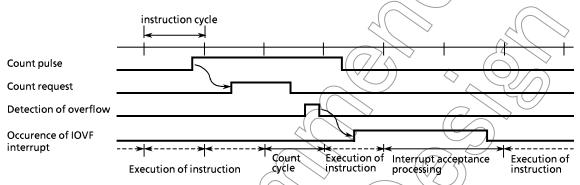


Figure 3-10. Timer/Counter Overflow Interrupt Timing

(1) Event counter mode

In the event counter mode, the timer/counter increments at each rising edge of the external pin (T1, T2) input. T1, T2 pins are shared by R83, R81 pins. Output latch of R83, R81, are set to "1" when used as timer/counter input. Also output latch is initialized "1" during reset. The maximum applied frequency of the external pin input is fc/32 for the 1-channel operation; for the 2-channel operation, the frequency is fc/32 for TC1 and fc/40 for TC2. The apparent instruction execution speed drops most to $(9/11) \times 100 = 82\%$ when TC1 and TC2 are operated at the maximum applied frequency because the count operation is inserted once every 4 instruction cycles for TC1 and every 5 instruction cycles for TC2. For example, the instruction execution speed of 2 μ s drops to 3.64 μ s. Example: To operate TC2 in the event counter mode.

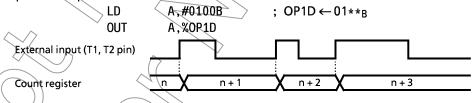


Figure 3-11. Event Counter Mode Timing Chart

(2) Timer mode

In the timer mode, the timer/counter increments at the rising edge of the internal pulse generated from the interval timer. One of 4 internal pulse rates can be selected by the command register. The selected rate can be initially set to the timer/counter to generate an overflow interrupt in order to crerate a desired time interval.

When an internal pulse rate of fc/2¹⁰ is used, a count operation is inserted once every 128 instruction cycles, so that the apparent instruction execution speed drops by (1/127) \times 100 = 0.8%. For example, the instruction execution speed of 2 μ s drops to 2.016 μ s. In the timer mode, R83 (T1) and R81 (T2) pins provide the ordinary I/O ports.

Example: To generate an overflow interrupt (at fc = 4 MHz) by TC1 after 100 ms.

LD HL,#0F4H ; $TC1 \leftarrow E79_H$ (Setting of count register)

ST #9,0HL+ ST #7,0HL+

ST #0EH,@HL+

LD A,#1000B ; OP1C \leftarrow 1010_B (Timer mode rate fc/210)

OUT A,%OP1C LD A.#0100B

A,#0100B; EIR < 0100B (Enables interrupt)

XCH A,EIR

EICLR IL,110111B ; EIF $\leftarrow 1$, 1L₃ $\leftarrow 0$

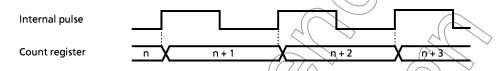


Figure 3-12. Timer Mode Timing Chart

* The apparent execution rate is calculated as following.

$$1 \div \{ \frac{\text{(Fundamental clock frequency)/8}}{\text{(Internal pulse rate)}} - 1 \} \times 100 \text{ [%]}$$

* Calculating the initial value of the count register

 2^{12} - (interrupt setting time) x (internal pulse rate)

For example, to generate an overflow interrupt after 100 ms at fc = 4 MHz with the internal pulse rate of $fc/2^{10}$, set the following value to the count register as the initial value:

$$2^{12} - (100 \times 10^{-3}) \times (4 \times 10^{6} / 2^{10}) = 3705 \text{ (E79H)}$$

(3) Pulse width measurement mode

In the pulse width measurement mode, the timer/counter increments with the pulse obtained by sampling the external pins (T1, T2) by the internal pulse. As shown in Figure 3-13, the timer/counter increments only while the external pin input is high. The maximum applied frequency to the external pin input must be one that is enough for analyzing the count value by program. Normally, a frequency sufficifient slower than the internal pulse ratesetting is applied to the external pin.

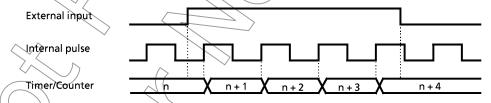


Figure 3-13. Pulse Width Measurement Mode Timing Chart

3.4 Pulse output

Pulse output is used for buzzer drive and remote control carrier. Pulse output is shared with the R71 pin. Pulse output is asynchronous.

3.4.1 Circuit Configuration

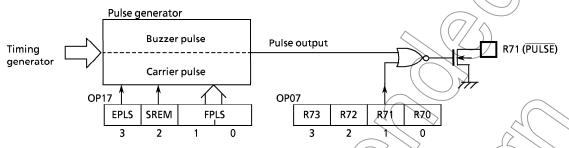


Figure 3-14. Pulse Generator

3.4.2 Control of pulse Output

The pulse output is controlled by the command register (OP17) and R71 output latch data (bit 1 of OP07). At reset, the OP17 is initialized to "0000B" and pulse output is disabled. To use the pulse output, instruct start/stop of pulse after pulse output is enabled by the OP17.

Also, pulse output is "L" level (the OP17 is cleared to "0000_B") during the HOLD operating mode. External LED and so foth may be destroyed if HOLD operation is executed during output of pulse. Therefore, HOLD operating mode should be execute after pulse is stopped (after R71 output latch set to "1").

Note: It is necessary to disable the pulse output circuit prior to enabling fs output mode.

Example: Buzzer pulse of 2 kHz is output (fc = 4 MHz)

LD A, #1001B

OÚT A, %OP17 ; OP17←1001_B

CLR %OP07, 1 ; Pulse start

Pulse output control (Port address: OP17) (Initial value: 0000)



0: Disable 1: Enable

SREM Selects output mode

0: Buzzer pulse (1/2 duty)

1: Remo-com carrier (1/3 duty)

00: fc/2¹², fc/(2² × 3) [Hz] 01: fc/2¹¹, fc/(2⁴ × 3)

10: $fc/2^{10}$, $fc/(2^5 \times 3)$

11: fc/2⁹, fs

Buzzer Carrier

Figure 3-15. Pulse Output Control

ν.	Tak	کرا	3_3	Dulco	Output	Frequency
_	170	и	7-7	PIIIVE		FIRMURIC

Ì	EDI C	Buzzer	pulse	Carrier pulse					
	FPLS	Pulse rate	at fc = 4.19 MHz	Pulse rate	frequency				
Ī	00	fc/2 ¹² [Hz]	1.024 [kHz]	fc/(2 ² ×3) [Hz]	37.9 [kHz] (fc = 455 kHz)				
ľ	01	fc/2 ¹¹	2.048	fc / (2 ⁴ × 3)	37.5 (fc = 1.8 MHz)				
1	10	fc / 2 ¹⁰	4.096	fc / (2 ⁵ × 3)	37.5 (fc = 3.6 MHz)				
ľ	11	fc / 2 ⁹	8.192	fs	_				

(1) Buzzer pulse

The buzzer pulse can be selected one of the four pulse rates by the program. The buzzer pulse is output only when the R71 output latch is "0". "H" level is output when the output latch is "1".

Note: When a piezoelectric buzzer is connected to the pin, voltage may be generated by the buzzer due to thermal or mechanical shock. In such cases, there is danger of the pin being destroyed so a zener diode should always be connected for protection.

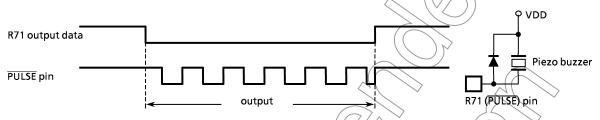


Figure 3-16. Circuit Example of Buzzer Pulse and Timing

(2) Carrier pulse for remote control signal transmitter

The remote control transmitting carrier has a frequency in table 3-3. The basic clock (fc) divided by 12, 48 and 96 is output respectively at 1/3 duty. Also, the remote control transmitting carrier is output only when the R71 output latch is "0". "H" level is output when the output latch is "1". When fs is selected as the output frequency. fs [Hz] is output at 1/2 duty.

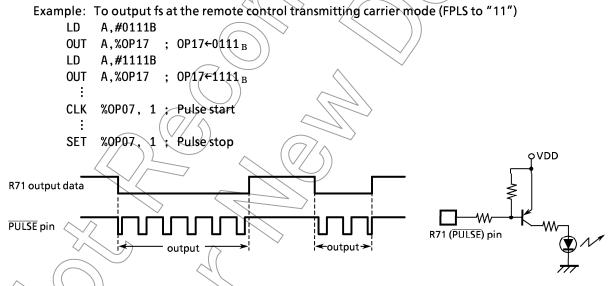


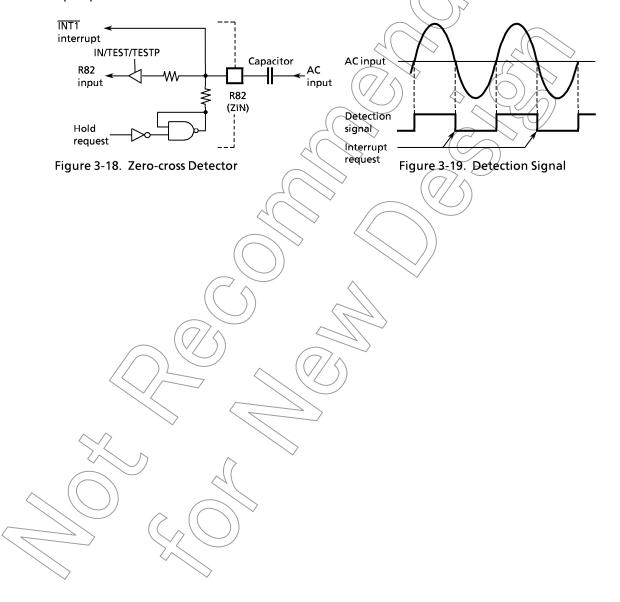
Figure 3-17. Circuit Example of Carrier Pulse and Timing

3.5 Zero-cross detector

R82 pin is used for zero-cross detection input (ZIN) and zero-cross detection can be performed by connecting and external capacitor. To use the zero-cross detector, the R82 output latch must be set to "1" (it is set to "1" during reset).

This function can be used for commercial power supply frequency input, and time base or triac control. ZIN pin is shared by the external interrupt 1. The INT1 interrupt occurs at the falling edge of the pin input by setting interrupt enable master flip-flop (EIF) to "1".

The zero-cross detector is disable and R82 pin is set to "H" level during the hold operating mode. When driving R82 pin directly without using an external capacitor, R82 is used for normal digital input or interrupt input.



3.6 AD Converter

TMP47C222/422 have a 8-bit successive approximate type AD converter and is capable of processing 4 analog inputs. Analog reference voltage can be cut off by command register (bit 3 of OP12). In the hold mode, analog reference voltage is cut off automatically.

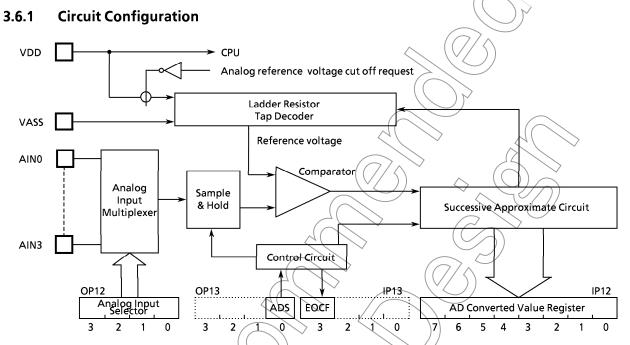


Figure 3-20. Block Diagram of AD Converter

3.6.2 Control of AD converter

The operation of AD converter is controlled by a command register (OP12, OP13, IP12, IP13).

(1) Analog input selector (QP12)
Analog inputs (AINO through AIN3) are selected by this register.

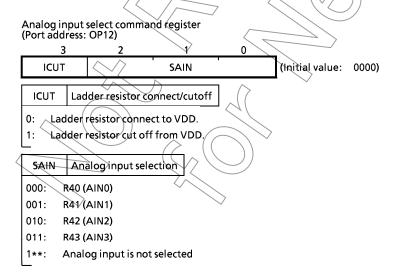


Figure 3-21. Analog Input Selector

(2) Start of AD conversion (OP13)

AD conversion is started when ADS is set to "1". After the conversion is started, ADS is cleared by hardware. If the restart is requested during the conversion, the conversion is started again at the time. Analog input voltage is hold by the sample hald circuit.

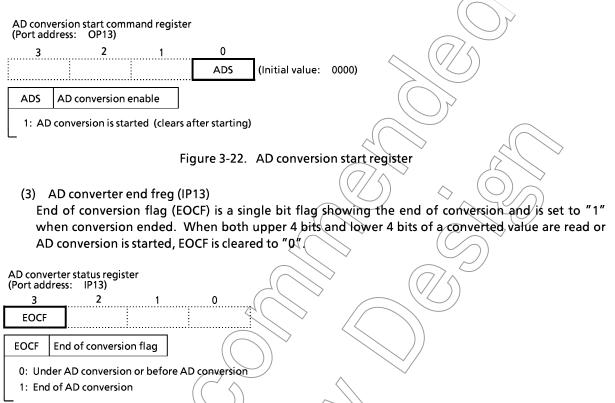


Figure 3-23. AD converter status register

(4) AD converted value register (IP12)

An AD converted value is read by accessing port address IP12. An AD converted value is read by splitting into upper 4 bits and lower 4 bits by a value of LR₀ (LSB of the L registers).

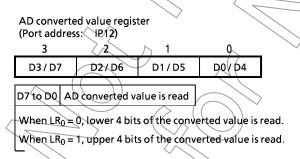


Figure 3-24. AD converted value register

3.6.3 How to use AD converter

Apply positive of analog reference voltage to the VDD pin and negative to the VSS pin. The AD conversion is carried out by splitting reference voltage between VDD and VSS to bit corresponding voltage by a ladder resistor and making a judgement by comparing it with analog input voltage.

(1) Start of AD conversion

Prior to conversion, select one of the analog input AIN0 through AIN3 by the analog input selector. Place output of the analog input, which is to be AD converted, in the high impedance state by setting "1". If other port is used as an output port, be careful not to execute the output instruction for any port during conversion in order to keep accuracy of conversion.

AD conversion is started by setting ADS (bit1 of the AD conversion start register). When conversion ends after 24 instruction cycles, EOCF showing the end of conversion is set to "1".

Analog input voltage is sampled during the following 2 instruction cycles after setting AD conversion enable.

Note: The sample and hold circuit has capacitor ($C_A = 12 \, \text{pF} \, \text{typ.}$) with resistor ($RA = 5 \, \text{k}\Omega \, \text{typ.}$). See I/O circuitry table. This capacitor should be charged or discharged within 2 instruction cycles.

(2) Reading of an AD converted value

After the end of conversion, read an AD converted value is read by splitting into lower 4 bits and upper 4 bits by the AD converted value register (IP12). Lower 4 bits of the AD converted value can be read when $LR_0 = 0$ and upper 4 bits when $LR_0 = 1$. Usually an AD converted value is stored in RAM by an instruction [IN %p, @HL]. Further, if an AD converted value is read during conversion, it becomes an indefinite value.

(3) AD conversion with HOLD operation

SLOOP :

LD

When the HOLD operation is started during the conversion, the conversion is terminated and an AD converted value becomes indefinite. Therefore, EOCF is kept clear to "0" after release from the HOLD operation. However, if the HOLD operation is started after the end of conversion (after EOCF has been set), AD converted value and status of EOCF are held.

Example: Selecting analog input (AIN3), starting AD conversion, monitoring EOCF, and storing lower 4 bits and upper 4 bits of a converted value to RAM [10_H] and RAM [11_H] respectively.

A, #3H

A, %0P12 **OUT** LD A, #1H ; Start of AD conversion **OUT** A, %OP13 %IP13, A ; To wait until EOCF goes to "1" IN **TEST** A, 3 \$L00P LD(HL, #10H ; HL ← 10_H ; RAM $[10_H] \leftarrow Lower 4 bits$ Иĸ %IP12, @HL JUC L ; Increment of L registers MI %IP12, @HL ; RAM $[11_H] \leftarrow Upper 4 bits$

; Selecting analog input (AIN3)

3.7 Serial Interface (SIO)

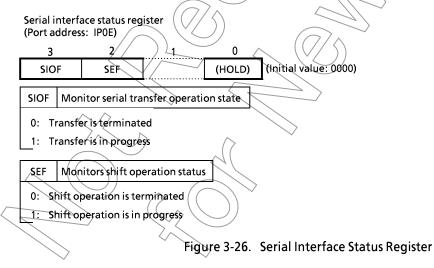
The TMP47C222/422 have a serial interface with an 8-bit buffer. 4-bit/8-bit tramsfer mode can be selected. In the 8-bit transfer mode, data may be transmitted and received simultaneously. The serial interface is connected to the exterenal device via 3 pins (the serial port): R92 (SCK), R91 (SO), and R90 (SI). The serial port is shared by port R9. For the serial port, the output latch of port R9 must be set to "1". In the transmit mode, R90 pin provides the I/O port; in the receive mode, R91 pin provides the I/O port.

3.7.1 **Configuration of Serial Interface** Figure 3-25. shows configuration of serial interface. 2nd access 1st accesss Transmit mode: OP0F Receive mode: Command register 1 Command register 2 5 OP1F Serial buffer IP0E Serial data Shift register Shift register output Controller (Shift counter) in 8-bit mode in 4-bit mode Serial data input Serial clock Serial data Interrupt request I/O (Buffer full or Buffer empty)

Figure 3-25 Configuration of Serial Interface

3.7.2 Control of Serial Interface

The serial interface is controlled by command registers (QP1E, QP1F) and the status register (IP0E).



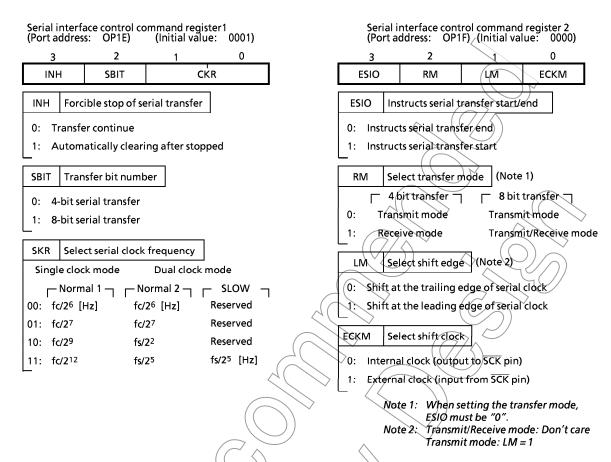


Figure 3-27. Serial Interface Control Command Register

3.7.3 Serial clock

For the serial clock, one of the following can be selected according to the contents of the command registers:

- (1) Clock source selection
 - a. Internal clock

The serial clock frequency is selected by command register 1.

The serial clock is output on the SCK pin. Note that the start of transfer, the SCK pin output goes high. This device provides the wait function in which the shift is not occurred until these processings are completed.

The highest transfer rate based on the internal clock is 93750 bits/second (at fc = 6 MHz).

b. External clock

The signal obtained by the clock supplied to the SCK pin from the outside is used for the serial clock. In this case, the output latch of R92 (SCK) must be set to "1" beforehand. For the shift operation to be performed correctly, each of the serial clock high and low levels needs 2 instruction cycles or more to be completed.

- (2) Shift edge selection
 - a. Leading edge

Date is shifted at the leading edge (the falling edge of SCK pin input) of the serial clock.

b. Trailing edge

Data is shifted at the trailing edge (the rising edge of SCK pin input) of the serial clock. However, in the transmit mode, the trailing-edge shift is not supported.

3.7.4 Transfer bit number

SBIT (bit 2 of the command register 1) can select 4-bit/8-bit serial transfer.

(1) 4-bit serial transfer

In this mode, transmission/reception is performed on 4-bit basis. ISIO interrupt is generated every 4-bit transfer. Transmit/receive data is written/read by accessing the buffer register (OP0F/IP0F) respectively.

(2) 8-bit serial transfer

In this mode, transmission/reception is performed on 8-bit basis. ISIO interrupt is generated every 8-bit transfer. Transmit /receive data is written / read by accessing the buffer register (OP0F / IP0F) twice.

At the first access after setting transfer mode or generating the interrupt request, the write/read operation of lower 4-bit is performed to from the buffer register. At the second access, that of upper 4-bit is performed.

3.7.5 Transfer modes

Selection between the transmit mode, the receive mode (at transferring 4 bit) and the transmit and receive mode (at transferring 8 bit) is performed by RM (bit 2 of the command register 2). Switching the transfer modes should be implemented after specifying the end of transferring (clears ESIO to "0") and conferring the end of transferring (ISOF).

(1) Transmit mode

The transmit mode is set to the command register than writes the first transmit data (4 bits or 8 bits) is written to the buffer register (OPOF). (If the transmit mode is not set, the data is not written to the buffer register). In the 8-bit transfer mode, the 8-bit data is written by accessing the buffer register (OPOF) twice. The transmit data is written after the 8-bit transfer mode is set or an interrupt request occurs: the lower 4 bits are written by the first access and the upper 4 bits by the next access. Then, setting ESIO to "1" starts transmission. The transmit data is output to the SO pin in synchronization with the serial clock from the LSB side sequentially. When the LSB is output, the transmit data is moved from the buffer register to the shift register. When the buffer register becomes empty, the buffer empty interrupt (ISIO) to request for the next transmit data is generated. In the interrupt service program, when the next transmit data tis written o the buffer register, the interrupt request is reset.

In the operation based on the internal clock, if no more data is set after the transmission of the 4-bit or 8-bit data, the serial clock is stopped and the wait state sets in. In the operation based on the external clock, the data must be set in the buffer register by the time the next data shift operation starts. Therefore, the transfer rate is determined by the maximum delay time between the occurrence of the interrupt request and the writing of data to the buffer register by the interrupt serviced program.

To end transmission, ESIO is cleared to "0" instead of writing the next transmit data by the buffer empty interrupt service program. When ESIO is cleared, transmission stops upon termination of the currently shifted-out data. The transmission end can be known by the SIOF state (SIOF goes "0" upon transmission end). In the operation based on the external clock, ESIO must be cleared to "0" before the next data is shifted out. If ESIO is not cleared before, the transmission stops upon sending the next 4-bit or 8-bit data (dummy).

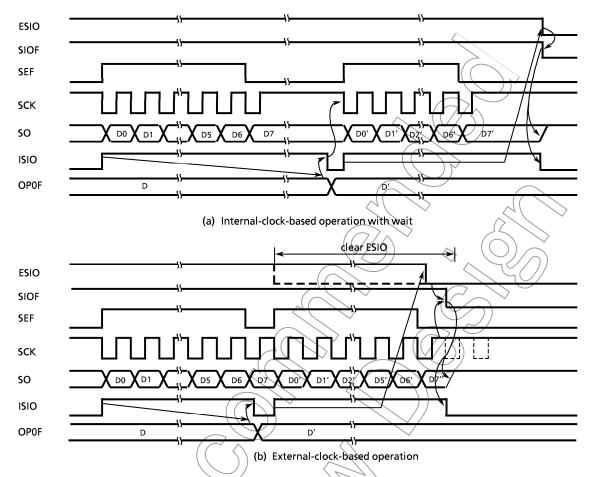


Figure 3-28. Transmit Mode

(2) 4-bit receive mode

Data can be received when ESIO is set to "1" after setting the receive mode to the command register. The data is put from the SI-pin to the shift register in synchronization with the serial clock. Then the 4/8-bit data is transferred from the shift register to the buffer register (IPOF), upon which the (buffer full) interrupt (ISIO) to request for reading received data is generated. The receive data is read from the buffer register by the interrupt service program. When the data has been read, the interrupt request is reset and the next data is put in the shift register to be transferred to the buffer register. In the operation based on the internal clock, if the previous receive data has not been read from the buffer register at the end of capturing the next data, the serial clock is stopped and the wait operation is performed until the data has been read. In the operation based on the external clock, the shift operation is performed in synchronization with the externally-suppliedclock, so that the data must be read from the buffer register before the next receive data is transferred to it. The maximum transfer rate in the external-clock-based operation is determined by the maximum delay time between the generation of interrupt request and the reading of receive data. In the receive mode, the shift operation may be performed at either the leading edge or the trasiling edge. In the leadingedge shift operation, data is captured at the leading edge of the serial clock, so that the first shift data must be put in the SI pin before the first serial clock is applied at the start of transfer.

Example: To instruct the receive start operation with the 4-bit serial transfer, internal clock and leadingedge shift (with the interrupt enable register already set).

```
LD A, #0000B; OP1E \leftarrow 0000B (Sets the 4-bit serial transfer)
```

OUT A. %OP1E

LD A, #0110B; OP1F \leftarrow 0110B (Sets the receive mode)

OUT A, %OP1F

EI ; EIF ← 1 (Enables interrupt)

LD A, #1110B ; ESIO ←1 (Instructs reception start)

OUT A, %OP1F

To end the receive operation, ESIO must be cleared to "0". When ESIO is cleared, the completion of the transfer of the current 4-bit data to the buffer register terminates the receive operation. To confirm the end of the receive operation by program, SIOF (bit 3 of the status register) must be sensed. SIOF goes "0" upon the end of receive operation.

Note: If the transfer modes are changed, the contents of the buffer register are lost. Therefore, the modes should not be changed until the last received data is read even after the end of reception is instructed (by clearing ESIO to "0").

The receive operation can be terminated in one of the following approaches determined by the transfer rate:

a. When the transfer rate is sufficiently low (the external-clock-based operation):

If ESIO can be cleared to "0" before the next serial clock is applied upon occurrence of buffer full interrupt in the external-clock-based operation, ESIO is cleared to "0" by the interrupt service program, then the last received data is read.

Example: To instruct reception and when transfer rate is low (leading-edge shift).

LD A, #0111B $ESIP \leftarrow 0$ (Instruct reception end)

OUT A, %OP1E

(IN %IPOF, A Acc ← IPOE (Reads received data)

b. When the transfer rate is high (the internal/external clock-based operation):

If the transfer rate is high and, therefore, it is possible that the capture of the next data starts before ESIO is cleared to "0" upon acceptance of any interrupt, ESIO must be cleared to "0" by confirming that SEF (bit 2 of the status register) is set at reading the data proceeding the last data. Then, the data is read. In the interrupt serevicing following the reception of the last data, no operation is needed for termination; only the reading of the received data is performed. This method is generally employed for the internal-clock-based operations. For an external-clock-based operation, ESIO must be cleared and the received data must be read before the last data is transferred to the buffer register.

Example: To instruct reception end when transfer rate is high (the internal clock, leading-edge shift).

SSEFO: TEST %IPOE, 2 ; Waits until SEF = "1"

B SSEF0

LD A, #0110B; ESIO \leftarrow 0

OUT A, %OP1F

IN %IP0F, A ; $Acc \leftarrow IP0F$ (Reads received data)

c. One-word reception

When receiving only 1 word, ESIO is set to "1" then it is cleared to "0" after confirming that SEF has gone "1". In this case, buffer full interrupt is caused only once, so that the received data is read by the interrupt service program.

Example: To instruct the start/end of 1-word reception (the internal clock, the trailing edge shift).

LD A, #0100B; OP1F \leftarrow 0100B (Sets in the receive mode)

OUT A, %OP1F

EI ; EIF ← 1 (Enables interrupt)

LD A, #1110B; ESIO < 1 (Instructs reception start)5

OUT A, %OP1F

SSEFO: TEST %IPOE, 2; Confirms that SEF = "1"

B SSEF0

LD A, #0110B \rightarrow ESIO \leftarrow 0 (Instructs reception end)

OUT A, %OP1F

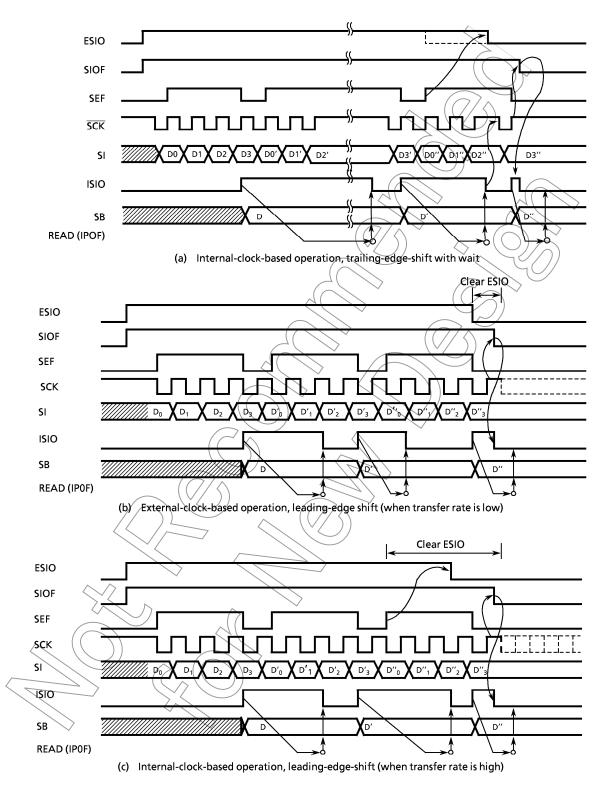


Figure 3-29. 4-bit Receive Mode

(3) 8-bit Transmit/Receive Mode

After setting the transmition/reception mode to the command register, write first transmit data into the buffer register. Then, when "1" is set to ESIO, data transmition/reception becomes possible. The transmit data is output to the SO pin at the leading edge of serial clock and the receive data is input from the SI pin at the trailing edge. If the shift register is filled with the receive data, the data is transferred to the buffer register and ISIO (buffer full) interrupt is generated to request data read. The received data is read from the buffer register by the interrupt service program, and then write the transmit data to the buffer register.

Lower order 4 bits of both transmit and receive data are read/written from/into the buffer register by first access after setting of transmition/reception mode or generation of ISIO and higher 4 bits by next access.

In the operation based on the internal clock, SIO becomes the wait state until the received data are read out and the next data to be transmitted are written.

In the operation based on the external clock, the shift operation is synchronized with the external clock; therefore, it is necessary to read the data received and to write data to be sent next before starting the next shift operation. The maximum transfer rate using an external clock is determined by the maximum delay time between the generation of the interrupt request and the writing of the data to be transmitted after the reading of the received data.

Also, the buffer register is used for both transmission and reception, therefore, the data must be written after reading 8 bits of receive data.

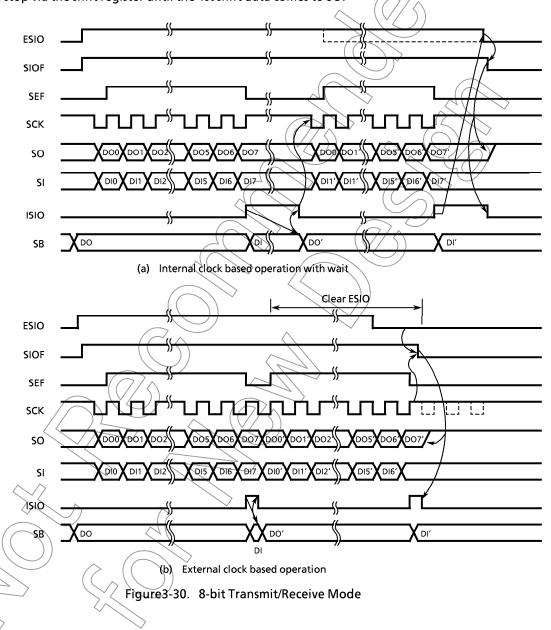
This operation is ended by clearing ESIO to "0". When ESIO is cleared, this operation is ended after transfer of the current 8 bits od data to the buffer register is completed. Programs can confirm that the operation has been completed by sensing SIOF (bit 3 of the status register) because SIOF is cleared to "0" when the operation is completed.



3.7.6 Stopping serial transfer

A serial transfer operation can be stopped forcibly.

It is stopped by setting INH (bit 3 of command register 1) to "1", clearing the shift counter. When the serial transfer is over, INH is automatically cleared to "0" with no other bits of command register affected. In the transmit mode of this case, \overline{SCK} and SO output are initialized to "H" level whereas the shift register is not cleared. Therefore, after the resumption of transmit, SO holds the data just before forcible stop via the shift register until the 1st shift data comes to SO.



3.8 LCD Driver

The TMP47C222/422 have the circuit that directly drives the liquid crystal display (LCD) and its control circuit.

The TMP47C222/422 have the following connecting pins with LCD.

- ① Segment output port 12 pins (SEG11 to SEG0)
- Segment output port (shared with I/O port) 8 pins (SEG19 to SEG12)
- ③ Common output port 4 pins (COM4 to COM1)

In addition, VLC pin is provided as the drive power pin.

The devices that can be directly driven is selectable from LCD of the following drive methods.

- 1 1/4 Duty (1/3 Bias) LCD Max 80 Segment (10 digits × 8 segments)
- 2 1/3 Duty (1/3 Bias) LCD Max 60 Segment (7 digits × 8 segments)
- 3 1/2Duty (1/2 Bias) LCD Max 40 Segment (5 digits x 8 segments)
- 4 Static LCD Max 20 Segment (2 digits × 8 segments)

3.8.1 Configuration of LCD driver

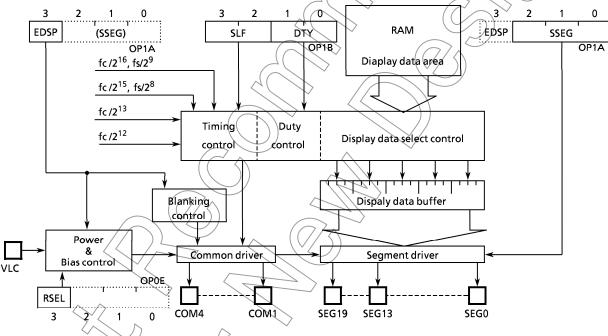


Figure 3-31. LCD Driver

3.8.2 LCD output resistance

LCD output resistance can be selected with using LCD display. Selecting of high / low resistance is executed by RSEL (bit 3 of OP0E). Output resistance is set to 20/200 $k\Omega$ during reset.

 (Port address: OP0E)
 (Initial value: 0000)

 3
 2
 1
 0

 RSEL
 LCD output resistance

0: Output resistance1 (20/200 kΩ)

Selection of output resistance

1: Output resistance2 (10/70 $k\Omega$)

Note: Bit 2 to 0 must be set to "0"

Figure 3-32. Command Register

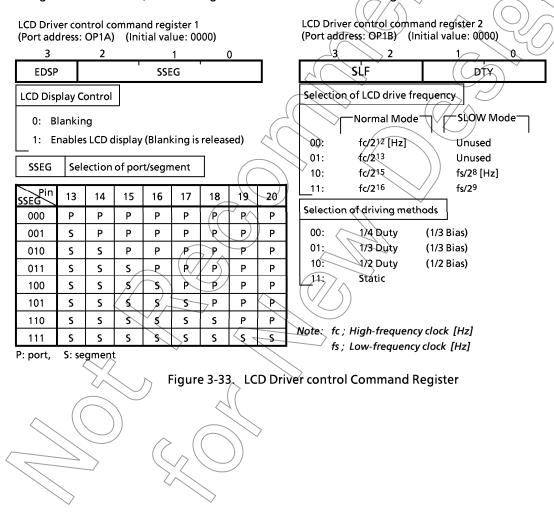
DCEI		Output hig	h resistance	
RSEL	Segment R _{OS1}	Common R _{OC1}	Segment R _{OS2}	Common R _{OC2}
0	20	kΩ	200) kis
1	10	kΩ	(//0	kΩ

Table 3-5. Selection of LCD output resistance

Note: The output resistance shows Typ. values (Topr = $25 \, ^{\circ}$ C, VDD = $5 \, \text{V}$)

3.8.3 Control of LCD driver circuit

The LCD driver is controlled by the command register 1,2 (OP1A, OP1B). Further, when the command register 2 is accessed, the most significant bit of the command register, 1 must be set to "0" (Blanking).



(1) Driving methods of LCD driver

Driving methods of LCD is selected 4 kind of DTY (bit 1 to 0 of command register 2). The drive method is initialized according to LCD used in the initial program.

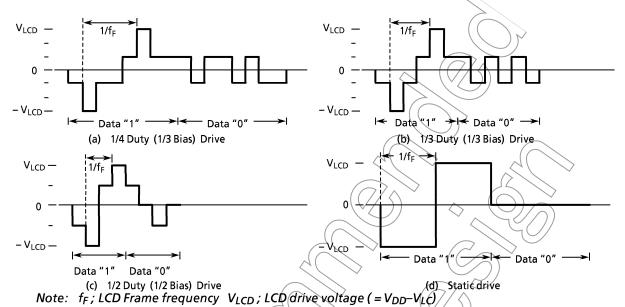


Figure 3-34. LCD drive wareform (Voltage COM-SEG Pins)



(2) Frame frequency

Frame frequency (f_F) is set according to the drive method and base frequency as shown in the following Table 3-6. The base frequency is selected by SLF (the lower 2 bits of the command register) according to the reference clock frequency fc and fs.

Table 3-6. Setting of LCD Frame Frequency

a. At the single clock mode

61.5	Dage Francisco (III-1		Frame Freq	uency [Hz]	
SLF	Base Frequency [Hz]	1/4 Duty	1/3 Duty	1/2 Duty	Static
11	fc 2 ¹⁶	fc	$\frac{4}{3} \cdot \frac{fc}{2^{16}}$	$\frac{4}{2} \cdot \frac{fc}{2^{16}}$	<u>fc</u> 2 ¹⁶
	(fc = 4 MHz)	61	81	122	61
10	fc 	fc	$\frac{4}{3} \left(\begin{array}{c} fc \\ \hline 2^{15} \end{array} \right)$	$\begin{array}{c} 4 \\ 2 \end{array} \cdot \begin{array}{c} fc \\ 2^{15} \end{array}$	fc, 2 ¹⁵
	(fc = 4 MHz)	122	163	244	122
01	fc 2 ¹³	fc 2 ¹³	$ \begin{array}{c c} 4 & fc \\ \hline 3 & 2^{13} \end{array} $	4 (fc 2 ¹³)	fc 2 ¹³
	(fc = 4 MHz)	488	651	977	488
00	fc 2 ¹²	fc 212	$\frac{4}{3}$ · $\frac{\text{fe}}{2^{12}}$	4 fc 2 2 ¹²	fc 2 ¹²
	(fc = 400 kHz)	98	130) 195	98

Note: fc; High-frequency clock [Hz]

b. At the dual clock mode

			Frame Freq	uency [Hz]	
SLF	Base Frequency [Hz]	1/4 Duty	1/3 Duty	1/2 Duty	Static
10	$\frac{fs}{2^9}$	- fs 29	4). fs 29	$\frac{4}{2} \cdot \frac{fs}{2^9}$	fs
	(fs = 32 kHz)	63	83	125	63
01	fs 28	<u>fs</u> 28	4 · fs 28	4 · fs 28	fs
	(fs=32 kHz)	125	167	250	125

Note: fs; Low-frequency clock [Hz]

(3) LCD drive voltage

The LCD drive voltage (V_{LCD}) is given by the difference in potential $(V_{DD}-V_{LC})$ between pins VDD and VLC. Therefore, when the CPU operating voltage and LCD drive voltage are the same, the VLC pin is connected to the VSS pin.

The LCDs light only when the difference in potential between the segment output and common output is $\pm V_{LCD}$, and turn off at all other times.

During reset, the power switch of the LCD driver is turned off automatically, shutting off the VLC voltage.

Both the segment output and common output become V_{DD} level at this time and the LCDs turn off. The power switch is turned on to supply VLC voltage to the LCD driver by setting EDSP (bit 3 of the command register 1) to "1_B". After that, the power switch will not turn off even during blanking (setting EDSP to "0") and the VLC voltage continues to flow.

The power switch is turned off during hold operation low power consumption by turning off the LCD. When hold operation is released the status in effect immediately before the hold operation is reinstated.

3.8.4 LCD display operation

(1) Display data setting

Display data are stored to the display data area (Max 20 words) in the data memory.

The display data stored to the display data area (address 20 to 33_H) are read automatically and sent to the LCD driver by the hardware.

The LCD driver generates the segment signals and common signals in accordance with the display data and drive method. Therefore, display patterns can be changed by only overwriting the contents of the display data area with a program. The table look up instruction is mainly used for this overwriting.

Figure 3-37 shows the correspondence between the display data area and the SEG/COM pins. The LCD light when the display data is "1" and turn off when "0".

The number of segment which can be driven differs depending on the LCD drive method therefore, the number of display data area bits used to store the data also differs. Consequently, data memory not used to store display data and data memory for which the addresses are not connected to LCD can be used to store ordinary user's processing data.

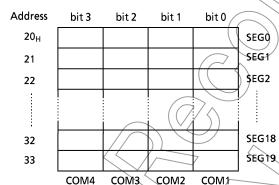


Table 3-7. Driving Method and Bit for Display Data

Driving methods	bit 3	bit 2	bit 1	bit 0
1/4 Duty	сом4	сомз	СОМ2	COM1
1/3 Duty	_	сомз	СОМ2	COM1
1/2 Duty	_	-	СОМ2	COM1
Static	_	-	_	COM1

Note: -; This bit is not used for display data.

Figure 3-35. LCD Display Data Area

(2) Blanking

Blanking is applied by setting EDSP to "0" and turns off the LCD by outputting the non light operation level to the COM pin.

The SEG pin continuously outputs the signal level in accordance with the display data and drive method.

With static drive, no voltage is applied between the COM and SEG pins when the LCD is turned off by data (display data cleared to "0"), but the COM pin output becomes constant at the $V_{LCD}/2$ level when turning off the LCD by blanking, so the COM and SEG pins are then driven by $V_{LCD}/2$.

3.8.5 Control method of LCD driver

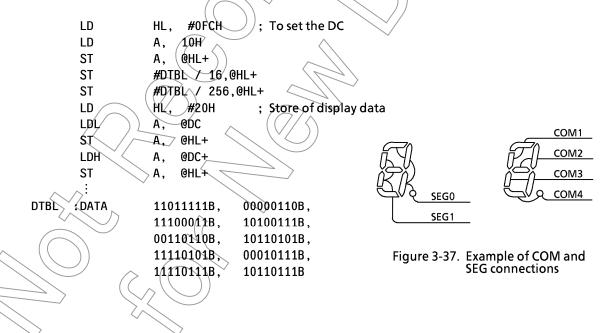
(1) Initial Setting

Flow chart of initial setting are as shown in Figure 3-36. Setting of segment driver Example: When operating the TMP47C422 with 1/4 duty LCD using a from frequency of fc/215 [HZ]. Setting of LCD drive method(DTY) and frequency (SLF) LD A, #0111; Blanking and all segment A, %OP1A OUT Setting of clear or initial value of display area in the data memory ; Setting 1/4 duty drive and frame LD A, #1000 frequency Display enable (EDSP) (Release of blanking) OUT A, %OP1B Setting of clear or intial value of display area in the data memory Figure 3-36. Initial setting of LD A, #1111B ; Display enable LCD driver OUT A, %OP1A ÷

(2) Store of display data

Normally, display data are kept permanently in the program memory and are then stored to the display data area by the table look-up instruction.

This can be explained using numerical display with 1/4 duty LCD as an example. The COM and SEG connections to the LCD are the same as those shown in Figure 3-37 and the display data are as shown in Table 3-8. Programming example for displaying numerals corresponding to BCD data stored at address 10_H in the data memory is shown below.



Display data Display data Numeral Display Numeral Display Upper Lower Upper Lower (101/1 0 1101 1111 5 0101 1/111 0000 0101 0110 6 1 2 1110 0011 7 0001 0111 1111 3 1010 0111 0111 8 0011 01/10 -101/1 4 0111

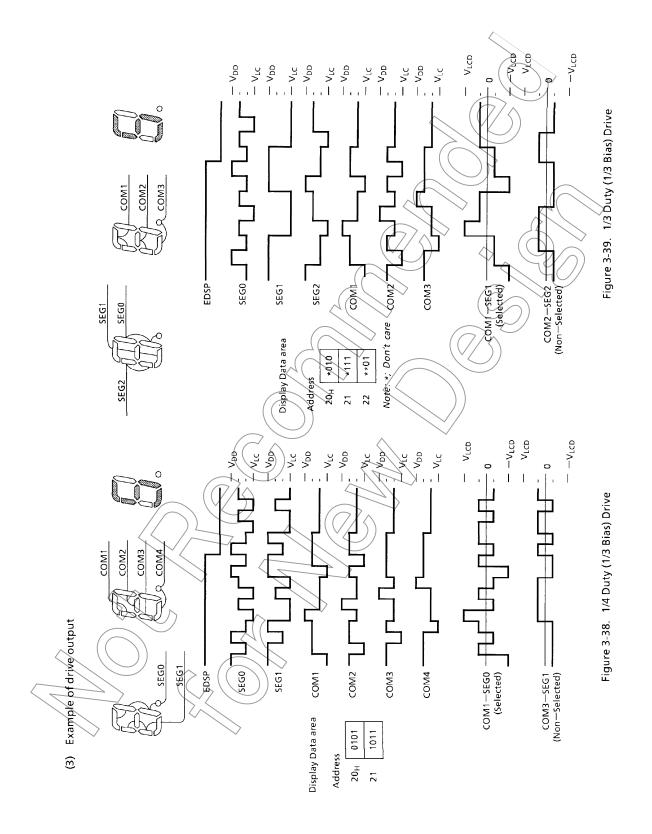
Table 3-8. Example of display data (1/4 Duty LCD)

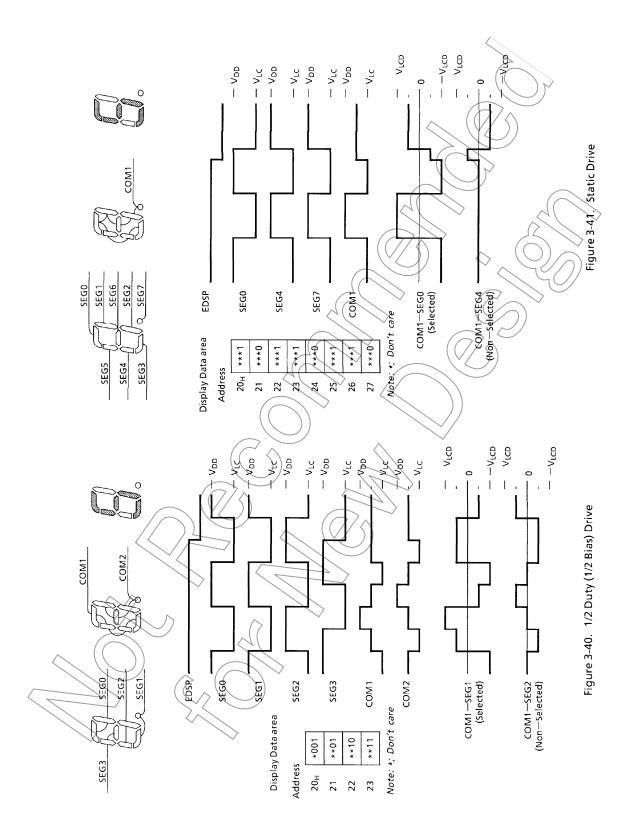
Table 3-9 shows the same numerical display used in Table 3-8, but using 1/2 duty LCD. The connections of the COM and SEG pins to the LCD are the same as those shown in Figure 3-40.

Table 3-9. Example of display data (1/2 Duty LCD)

Numeral		Displa	y data		Numeral	Display data						
Numeral	Upp	er	Lo	ower (Tullieral	Upp	er	Lo	ower			
0/	**01	Z**11	**01	**11	5	**11	**10	**01	**01			
1	**00	**10 <	**00	**10	> 6	**11	**11	**01	**01			
2	**10	**10	**01	**11	7	**01	**10	**00	**11			
3	**10	**01	**01	**11	8	**11	**11	**01	**11			
4	**11	**10	**00	**10	9	**11	**10	**01	**11			

Note: *; Don't care





6-22-61 2000-10-19

Port Condition by RESET Operation

The transition of Port condition by RESET operation is shown as below.

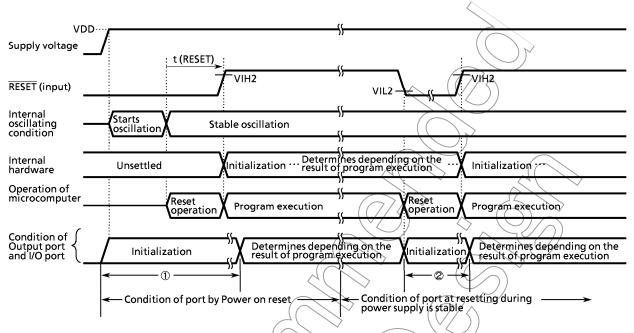
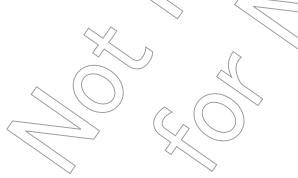


Figure 3-42. Port condition by Reset operation

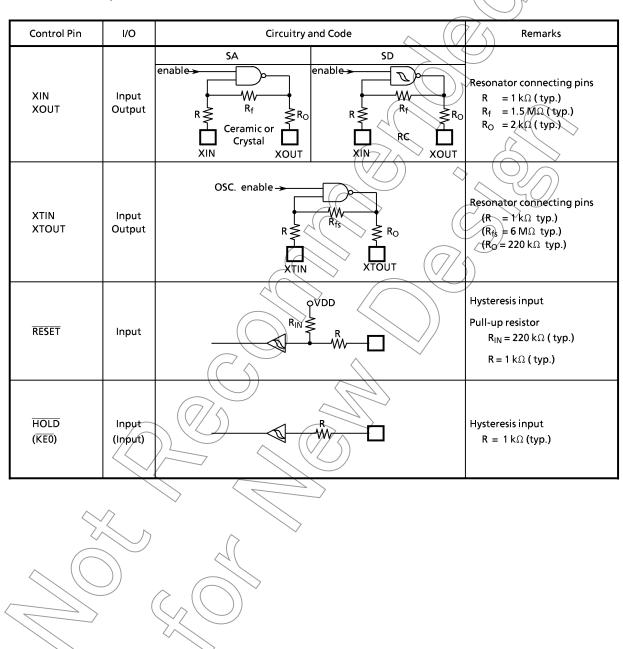
- Note 1: t(RESET) > 24/fc
- Note 2: VIL2: Stands for low level input voltage of RESET pin.
 - VIH2: Stands for high level input voltage of RESET pin.
- Note 3: The term from power on reset to the time program is executed (above ①) and also the term starting from reset operation during power supply is stable to the program is executed (above ②), the port is on the initial condition. The initial condition of Port differs from I/O circuit by each port, refer to the section of "INPUT/OUTPUT CIRCUITRY". Thus, when using Port as an output pin, in the term of the above ① and ②, the voltage level on the signal that connects with the output pin of Port to the input pin of external application circuit should be determined by the external circuitry such as pull-up resistor and / or pull-down resistor.



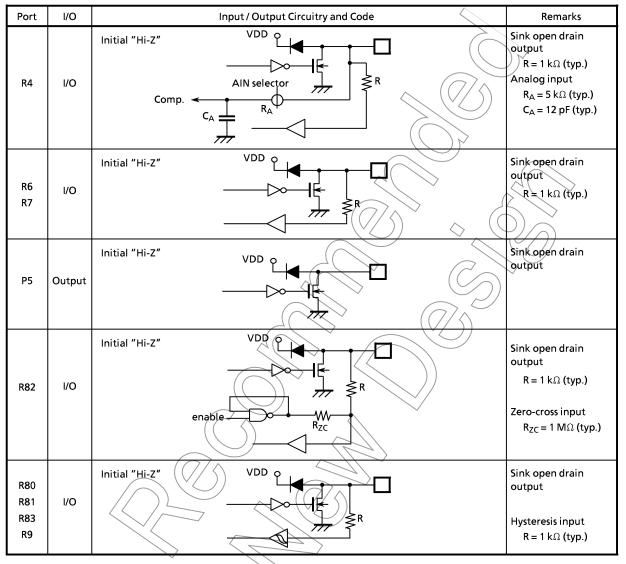
Input / Output Circuitry

The input/output circuitries of the TMP47C222/422 are shown as below, any one of the circuitries can be chosen by a code (SA, SD) as a mask option.

(1) Control pins



(2) I/O ports





Electrical Characteristics

Absolute Maximum Ratings $(V_{SS} = 0 V)$

Parameter	Symbol	Pins	Ratings	Unit
Supply Voltage	V_{DD}		-0.3 to 6.5	V
Input Voltage	V_{IN}	\ (\(\)	$\triangle 0.3 \text{ to V}_{DD} + 0.3$	V
Output Voltage	V _{OUT}		-0.3 to $V_{DD} + 0.3$	V
Output Current (Per 1 pin)	I _{OUT1}	Port R4, R7	30	mA
Output Current (Per 1 pin)	I _{OUT2}	Port R5, R6, R8, R9	3.2	mA
Power Dissipation [Topr = 70°C]	ZI _{OUT1}	Port R4, R7	120	mW
Power Dissipation [Topr = 70 C]	PD		400	mvv
Soldering Temperature (time)	Tsld	~	260 (10 s)	°C
Storage Temperature	Tstg		- 55 to 125	°C
Operating Temperature	Topr		- 30 to 70	°C

Note: The absolute maximum ratings are rated values which must not be exceeded during operation, even for an instant.

Any one of the ratings must not be exceeded. If any absolute maximum rating is exceeded, a device may break down or its performance may be degraded, causing it to catch fire or explode resulting in injury to the user. Thus, when designing products which include this device, ensure that no absolute maximum rating value will ever be exceeded.

Recommended Operating Conditions

 $(V_{SS} = 0 \text{ V}, \text{ Topr} = -30 \text{ to } 70^{\circ}\text{C})$

Parameter	Symbol	Pins	Conditions	Min	Max	Unit
			fc = 8.0 MHz	2.7		
Supply Valtage	W		(c)= 4.2 MHz	2.2	5.5	_v
Supply Voltage	V_{DD}		In the SLOW mode	2.2	5.5	
			In the HOLD mode	2.0		
	V _{IH1} ((Except Hysteresis Input	In the normal	$V_{DD} \times 0.7$		
Input High Voltage	V _{(H2}	Hysteresis Input	operating area	$V_{DD} \times 0.75$	V_{DD}	V
	V _{IH3}		In the HOLD mode	$V_{DD} \times 0.9$		
	/y <u>⊩</u>	Except Hysteresis Input	n the normal		$V_{DD} \times 0.3$	
Input Low Voltage	$\bigvee V_{IL2}$	Hysteresis Input	operating area	0	$V_{DD} \times 0.25$	V
	V _{IL3}		In the HOLD mode		$V_{DD} \times 0.1$	
^ ^	,		$V_{DD} = 2.7 \text{ to } 5.5 \text{ V}$		8.0	
Clask Francisco	fc	XIN, XOUT	$V_{DD} = 2.2 \text{ to } 5.5 \text{ V}$	0.4	4.2	
Clock Frequency)	\wedge	In the RC oscillation		2.5	MHz
	fs	XTIN, XTOUT	$V_{DD} = 2.2 \text{ to } 5.5 \text{ V}$	30	34	

Note: The recommended operating conditions for a device are operating conditions under which it can be guaranteed that the device will operate as specified. If the device is used under operating conditions other than the recommended operating conditions (supply voltage, operating temperature range, specified AC/DC values etc.), malfunction may occur. Thus, when designing products which include this device, ensure that the recommended operating conditions for the device are always adhered to.

DC Characteristics

 $(V_{SS} = 0 \text{ V}, \text{ Topr} = -30 \text{ to } 70^{\circ}\text{C})$

Parameter	Symbol	Pins	Conditions	Min	Тур.	Max	Unit
Hysteresis Voltage	V _{HS}	Hysteresis Input			0.7	-	٧
Input Current	I _{IN1}	RESET, HOLD	$V_{DD} = 5.5 \text{ V}, V_{IN} = 5.5 \text{ V}, 0 \text{ V}$	$\left(\right)$		± 2	μA
input current	I _{IN2}	Open drain output ports	VDD = 3.3 V, VIN = 3.5 V 0 V		_	± Z	μΑ
Input Resistance	R _{IN}	RESET		100	220	450	kΩ
Output Leakage Current	I _{LO}	Open drain output ports	$V_{DD} = 5.5 \text{ V}, V_{OUT} = 5.5 \text{ V}$	_	6	2	μΑ
Output Low Current	l _{OL}	Port R4, R7	$V_{DD} = 4.5 \text{ V}, V_{QL} = 1.0 \text{ V}$	7 (10	71	mA
Output Low	.,		V _{DD} = 4.5 V, I _{QL} = 1.6 mA	4		0.4	,,
Voltage	V _{OL}	Port P5, R6, R8, R9	V _{DD} = 2.2 V, I _{OL} = 20 μA		4	0.1	٧
Segment Output Low Resistance	R _{OS1}	SEG pin)/(10		
Common Output Low Resistance	R _{OC1}	COM pin		$(\overline{\mathcal{I}})$	or 20	_	kΩ
Segment Output High Resistance	R _{OS2}	SEG pin			70		
Common Output High Resistance	R _{OC2}	COM pin	$V_{DD} = 5 V$, $V_{DD} - V_{LC} = 3 V$	_	or 200	_	kΩ
	V _{O2/3}			3.8	4.0	4.2	
Segment/Common Output Registance	V _{O1/2}	SEG / COM pin		3.3	3.5	3.7	v
	V _{O1/3}			2.8	3.0	3.2	
			V _{DD} = 5.5 V, fc = 4 MHz	-	2	4	
Supply Current (in the Normal mode)	I _{DD}		$V_{DD} = 3.0 \text{ V}, \text{ fc} = 4 \text{ MHz}$	I	1	2	mA
			V _{DD} = 3.0 V, fc = 400 kHz	1	0.5	1	
Supply Current (in the SLOW mode)	loos		V _{DD} = 3.0 V, fs = 32.768 kHz	-	20	40	μΑ
Supply Current (in the HOLD mode)	I _{DDH}		V _{DD} = 5.5 V	-	0.5	10	μΑ

Note 1: Typ. values show those at Topr = 25° C, $V_{DD} = 5^{\circ}$ V.

Note 2: Input Current I_{IN1}: The current through resistor is not included.

Note 3: Output Resistance Ros, Roc; Shows on-resistance at the level switching.

Note 4: $V_{O2/3}$, Shows 2/3 level output voltage, when the 1/4 or 1/3 duty LCD is used.

V_{01/2}; Shows 1/2 level output voltage, when the 1/2 duty or static LCD is used.

V_{O1/3}; Shows 1/3 level output voltage, when the 1/4 or 1/3 duty LCD is used.

Note 5: Supply Current I_{DD} , I_{DDH} : $V_{IN} = 5.3 \text{ V} / 0.2 \text{ V} (V_{DD} = 5.5 \text{ V})$, 2.8 V / 0.2 V ($V_{DD} = 3.0 \text{ V}$)

Supply Current I_{DDS} , $V_{IN} = 2.8 \text{ V} / 0.2 \text{ V}$. Low frequency clock is only osillated.

Note 6: When using LCD, it is necessary to consider values of Ros 1/2 and Roc 1/2.

Note 7: Times fou SEG/COM output switching on; Ros1, Roc1: 2/fc (s)

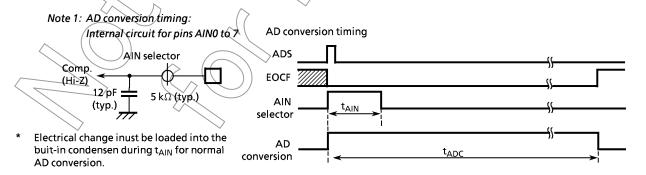
Ros2, Roc2: $1/(n \cdot f_F)$ (1/n; duty, f_F : frame frequency)

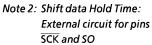
AD Conversion Characteristics

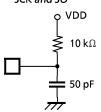
 $(Topr = -30 \text{ to } 70^{\circ}C)$

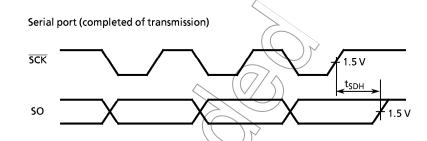
Parameter	Symbol	Conditions	Min	Typ.	Max	Unit
Analog Reference Voltage Range	△V _{AREF}	V _{DD} - V _{SS}	2.7	(-)	7	V
Analog Input Voltage	V _{AIN}		Vss)/<	V _{DD}	V
Analog Supply current	I _{REF}		\ <u>-</u> \	0,5	1.0	mA
Nonlinearity Error				_	± 1	
Zero Point Error		$V_{DD} = 2.7 \text{ V to } 5.5 \text{ V}$		_	± 1	
Full Scale Error		$V_{SS} = \pm 0.000 V$		- /	(±1)	LSB >
Total Error			<u> </u>	-, [2	±2,	,

AC Characteristics	$(V_{SS} = 0 \text{ V, Topr} = -30 \text{ to } 70^{\circ}\text{C})$							
Parameter	Symbol	Con	ditions	Min	Typ.)	Max	Unit	
Instruction Cycle Time	tcy	In the normal mode	$V_{DD} = 2.7 \text{ to } 5.5 \text{V}$ $V_{DD} = 2.2 \text{ to } 5.5 \text{V}$ RC oscillation	1,0	-	20	μs	
		In the \$LOW mode		235		267		
High level clock pulse width	twch	For external	V _{DD} ≥ 2.7 V	60				
		clock	V _{DD} <2.7 V	120	_	_	ns	
Low level clock pulse width		^	V _{DD} ≩2.7V					
	twcL	(XIN input)	V _{DD} <2.7 V	120				
AD Conversion Time	t _{ADC}			-	24 tcy	1		
AD Sampling Time	t _{AIN}			_	2 tcy	-	μ s	
Shift data Hold Time	t _{SDH}			0.5 tcy – 0.3	-	_	μ s	





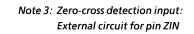


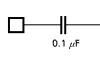


Zero-Cross Detection Characteristics

(Vss = 0V, Topr = -30 to 70° C)

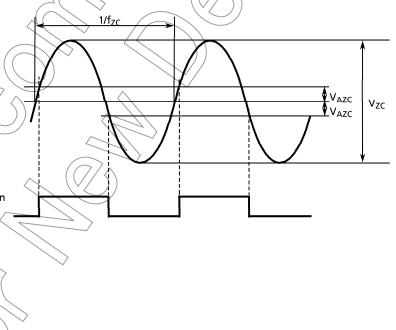
Parameter	Symbol	Conditions	Min	⟨> Тур. (Max	Unit
Zero-cross Input Voltage	V _{ZC}	AC coupling (C = 0.1 µF)	1.0		3,0	V _{P-P}
Zero-cross Accuracy	V _{AZC}	$f_{ZC} = 50 \text{ to } 60 \text{ Hz (sine curve)}$	_	(C_{2})	± 135	mV
Zero-cross input frequensy	f _{ZC}		40		1000	Hz









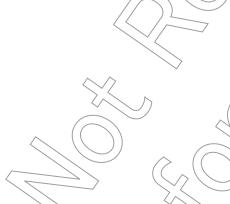


Recommended Oscillating Conditions

 $(V_{SS} = 0 \text{ V}, V_{DD} = 2.2 \text{ to } 5.5 \text{ V}, \text{ Topr} = -30 \text{ to } 70^{\circ}\text{C})$

XOUT (1) 6 MHz **Ceramic Resonator** 6 MHz) or 4<u>M</u>Hz CSA6.00MGU (MURATA) $C_{XIN} = C_{XOUT} = 30 pF$ $C_{XIN} = C_{XOUT} = 30 pF$ KBR-6.00MS (KYOCERA) EFOEC6004A4 (NATIONAL) CXIN = CXOUT = 30 pF **C**XOUT (2) 4 MHz **Ceramic Resonator** XOUT XIN CSA4.00MG (MURATA) $C_{XIN} = C_{XOUT} = 30 pF$ KBR-4.00MS (KYOCERA) $C_{XIN} = C_{XOUT} = 30 pF$ EFOEC4004A4 (NATIONAL) $C_{XIN} = C_{XOUT} = 30 pF$ **≹**Rxo∪⊤ 400 kHz **Crystal Oscillator** 204B-6F 4.0000 (TOYOCOM) $C_{XIN} = C_{XOUT} = 20 \text{ pF}$ C_{XIN} **C**XOUT (3) 400 kHz NITX ⁄x/tout **Ceramic Resonator** $C_{XIN} = C_{XOUT} = 220 pF$, $R_{XOUT} = 6.8 k\Omega$ CSB400B (MURATA) 32.768 kHz KBR-400B (KYOCERA) $C_{XIN} = C_{XOUT} = 100 \text{ pF}, R_{XOUT} = 10 \text{ k}\Omega$ EFOA400K04B (NATIONAL) $C_{XIN} = C_{XOUT} = 470 \text{ pF}, R_{XOUT} = 0.02$ CXTOUT π (4) 32.768 kHz XOUT C_{XTIN}, C_{XTOUT}; 10 to 33 pF (Note) **Crystal Oscillator** RC (5) RC Oscillation (V_{SS} = 0 V, V_{DD} = 5.0 V, $T_{opr} = 25^{\circ}$ C) W 2 MHz (Typ.) $C_{XIN} = 33 \text{ pF}, R_X = 10 \text{ k}\Omega$ Rx 400 kHz (Typ.) $C_{XIN} = 100 \text{ pF, } R_X = 30 \text{ k}\Omega$

Note: In order to get the accurate oscillation frequency, the adjustment of capacitors must be required.



Typical Characteristics

